Fourth Quarter FY 2025 Quarterly Update

Infineon Technologies AG
Investor Relations

Infineon at a glance

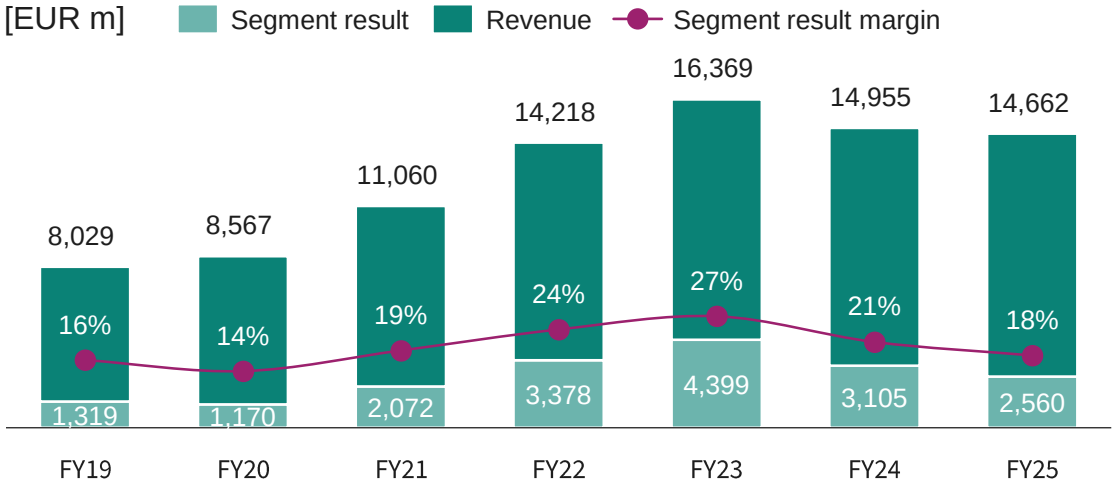
Addressing long-term high-growth trends

Energy
green and efficient

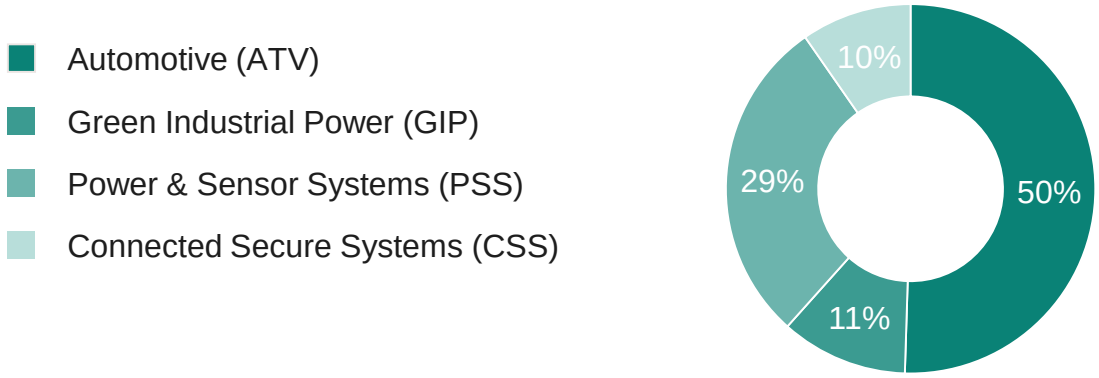
Mobility
clean and safe

IoT
smart and secure

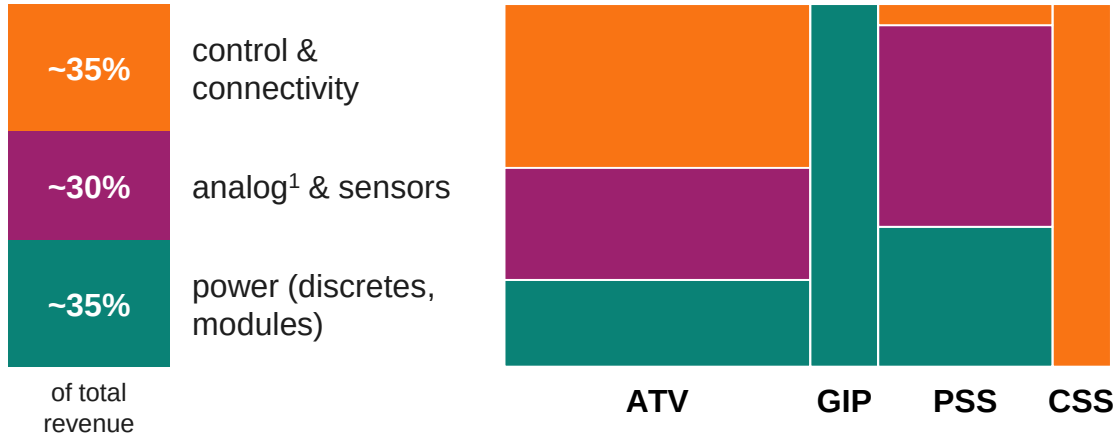
Financials



FY25 revenue by segment



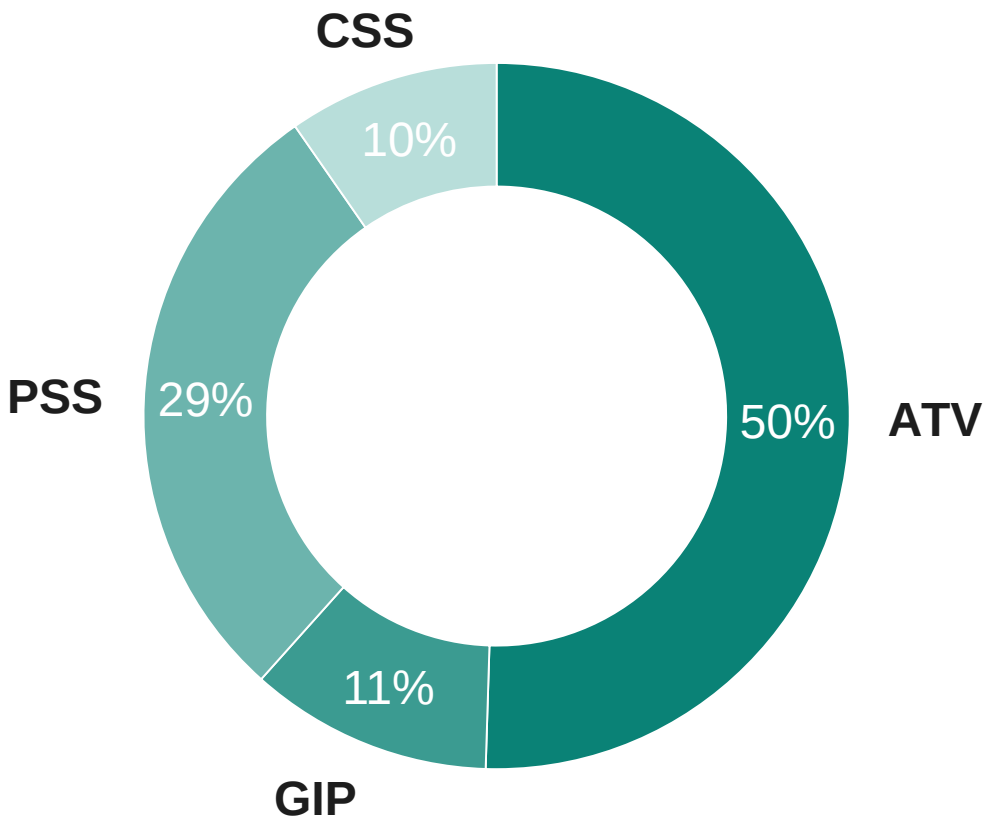
FY25 revenue by product category

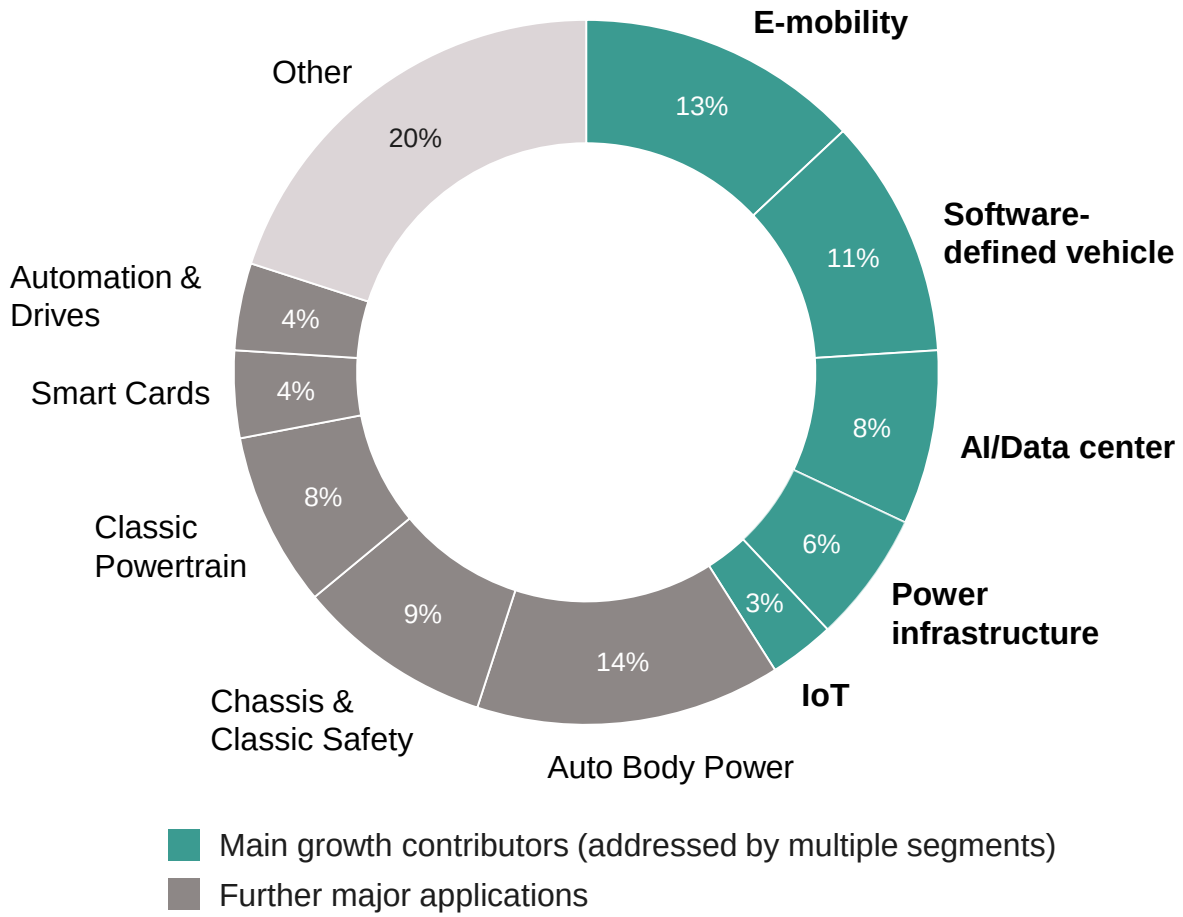


[1] including <5% of differentiating memory technologies

Well-balanced portfolio among segments and key applications, highest growth coming from Decarbonization and Digitalization

FY25 revenue of €14,662m by segment and key application

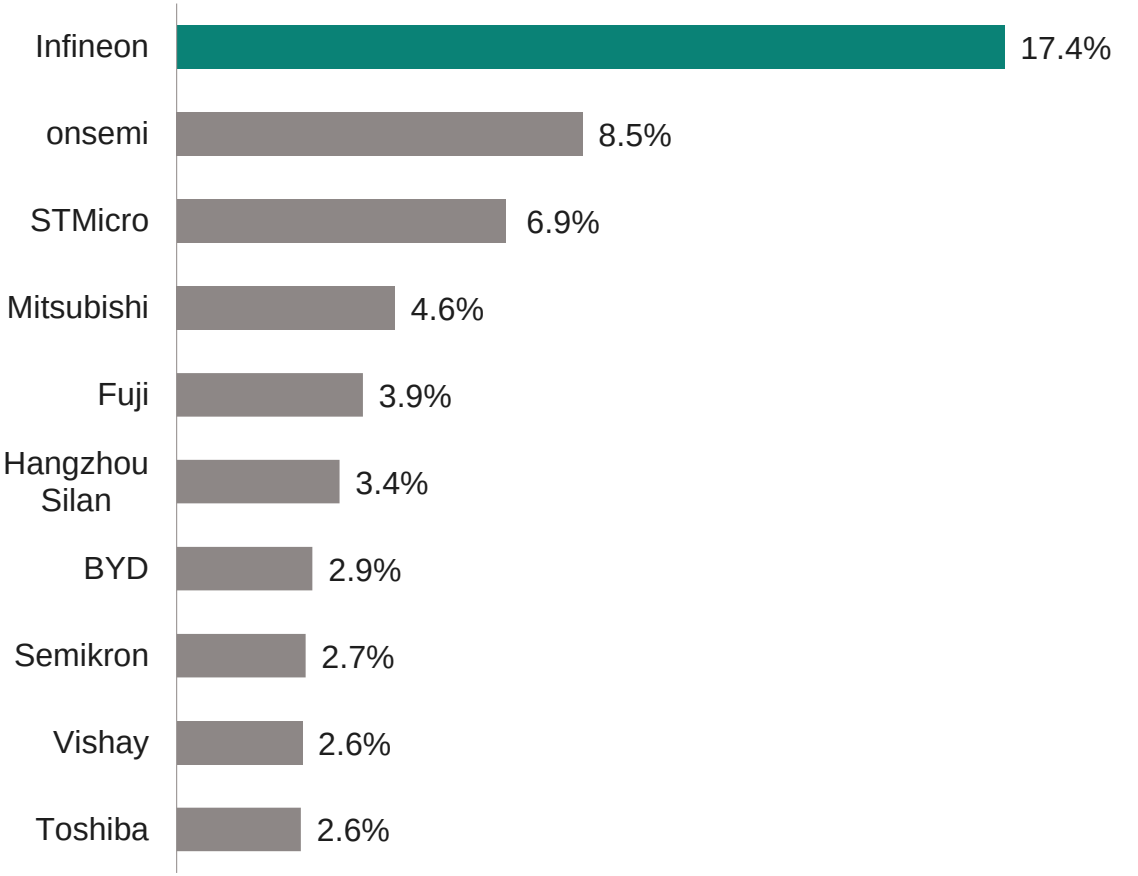




Infineon is a global player, clear #1 in power semiconductors, Automotive semis and automotive microcontroller markets

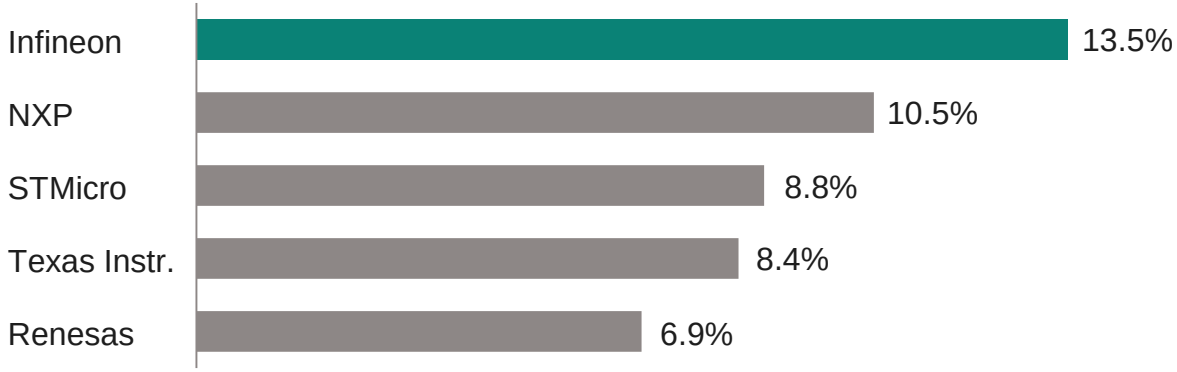
Power discretes and modules

2024 total global market: $32.8bn[1]

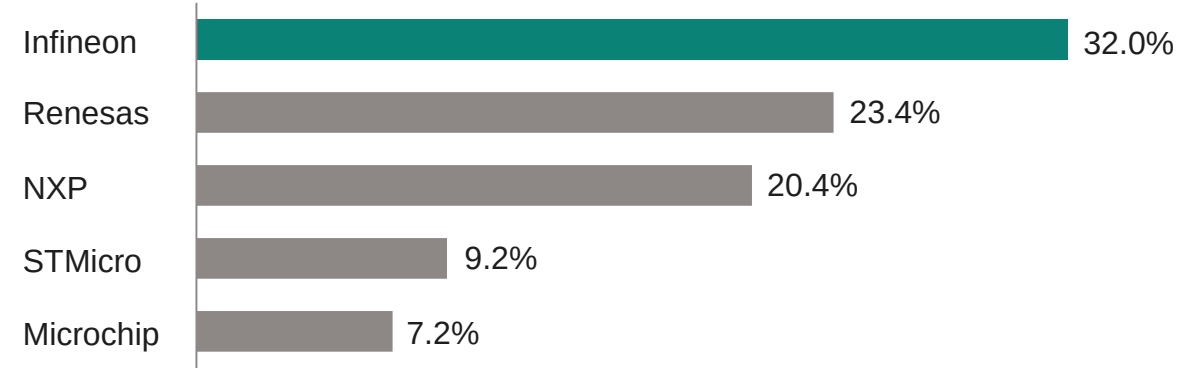


Automotive semiconductors

2024 total market: $68.4bn[2]



Automotive MCUs



[1] Based on or includes research from Omdia: *Power Semiconductor Market Share Database – 2*H25 (2024 Base Year). October 2025. | Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk. [2] Based on TechInsights: *Automotive Semiconductor Vendor Market Shares*. March 2025.

Our Target Operating Model: committing to ambitious financial goals and being the sustainability leader

Target Operating Model
through cycle

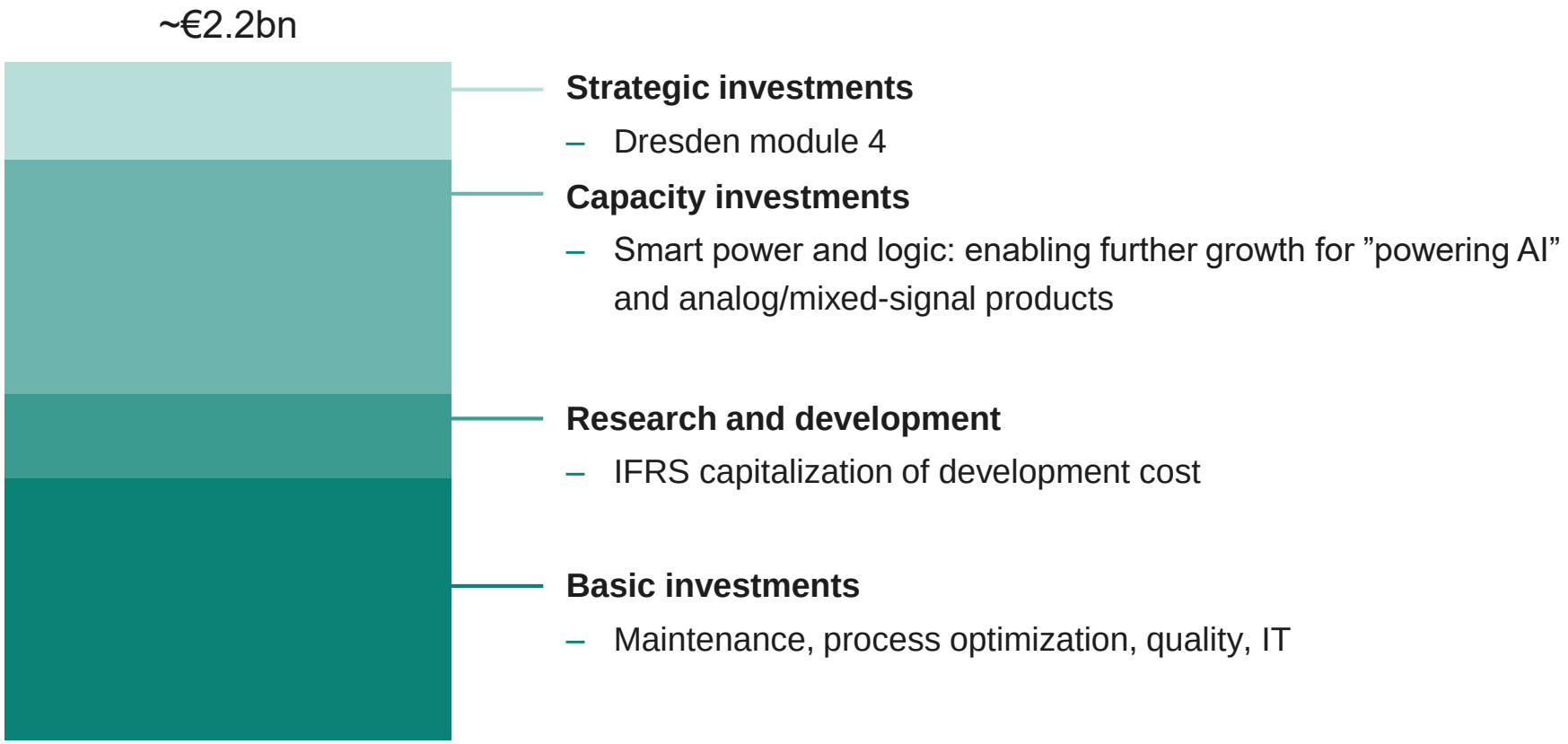
Revenue growth	**>10%**
Segment Result Margin	**25%**
Adj. Free Cash Flow Margin[1]	**10-15%**

Sustainability leader
CO_2 neutrality 2030

[1] See notes for definition

Modular investment approach allows ramp-up in line with market demand to ensure long-term value creation

Infineon investments[1] FY26



[1] Investments are defined as the total amount invested in property, plant and equipment and in other intangible assets, including capitalized development costs

Outlook for Q1 FY26 and FY26

	Outlook Q1 FY26[1]	Outlook FY26[1]
Revenue	~€3.6bn	moderately up vs. prior year
Adj. Gross Margin		low 40s %
Segment Result Margin	mid-to-high-teens %	high-teens %
FCF **Adj. FCF**		~€1.1bn/ ~€1.6bn
Investments		~€2.2bn
D&A		~€2.0bn[2]

[1] Based on an assumed average exchange rate of $1.15 for €1.00
[2] Including the amortization of approximately 400 million Euros from purchase price allocations

Undisputed power systems leadership mastering all three key materials

- Reliable multi sourcing of raw materials
- World-scale fabs

Controller → **Driver IC** → **Power switch** (Si/SiC/GaN)

Software + Algorithms

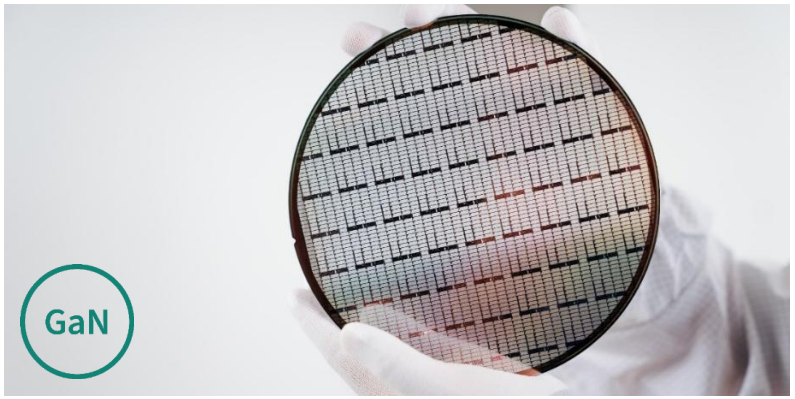
- Application understanding
- Packaging know-how and hybridization competence

Leadership in Power Systems across all materials and technologies

Silicon
Diode – MOSFET – IGBT – Driver – Controller

Silicon carbide
Diode – MOSFET

Gallium nitride
HEMT – Driver



Infineon is the leader across all power semiconductor technologies – unparalleled portfolio and know-how

Si

World's thinnest silicon power wafer with **20 µm** on **300 mm**

- Broadest Si-power portfolio in the market
- Unmatched quality and leading in all figures of merit (FOM)
- Best price/performance ratio

CoolMOS™ OptiMOS™

SiC

World's most competitive 200 mm silicon carbide power fab

- Broadest portfolio covering auto and industrial applications
- Leading trench performance
- High reliability and robustness in extreme conditions
- Smaller system size

CoolSiC™

GaN

World's first 300 mm gallium nitride power wafer

- Enabling cost parity with silicon
- Highest efficiency at the highest frequency enabling smallest system size
- Allow functional integration

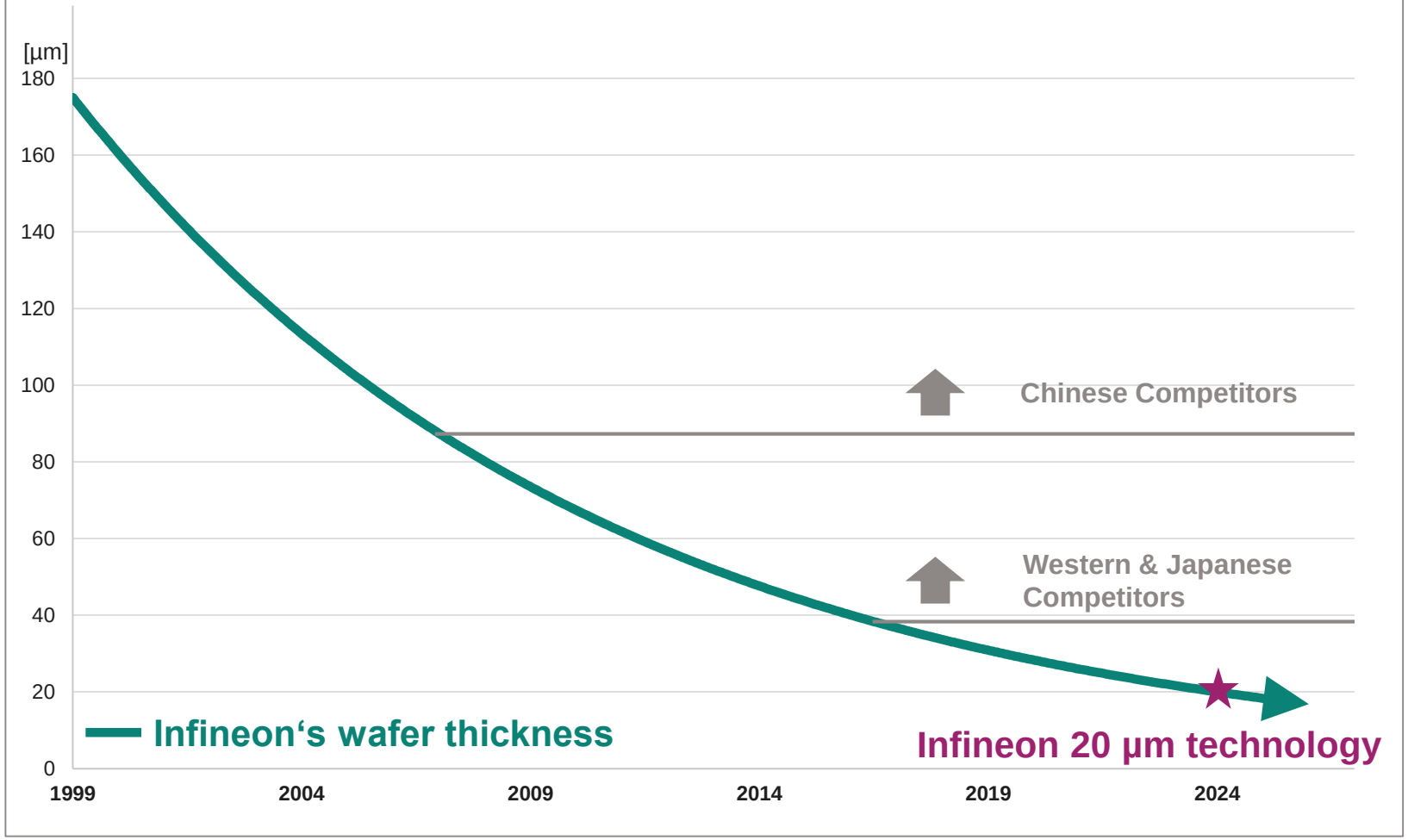
CoolGaN™

Infineon is strengthening its position as the industry's innovation leader leading the way in all three power semiconductor materials

Infineon presents the world's thinnest silicon power wafer paving the way for more energy efficient power systems

Si

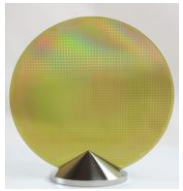
Infineon reduces wafer thickness from 40 µm to 20 µm



- Infineon pioneers 20 µm process at high-scale production
- Halving thickness also halves resistance, reducing power loss by >15%
- Enables easy and robust signal routing from front to backside
- Technology qualified by customers and applied in Infineon's Integrated Smart Power Stages for DC-DC converter in AI servers

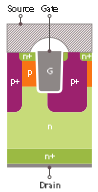
With Kulim 3, Infineon is on track to becoming the industry's most competitive provider of SiC technology

SiC



SiC raw material supplier network

- More than 6 qualified SiC wafer and boule suppliers
- Globally diversified and resilient



Superior trench technology

- 30% more chips per wafer than planar
- Unmatched reliability with zero field returns

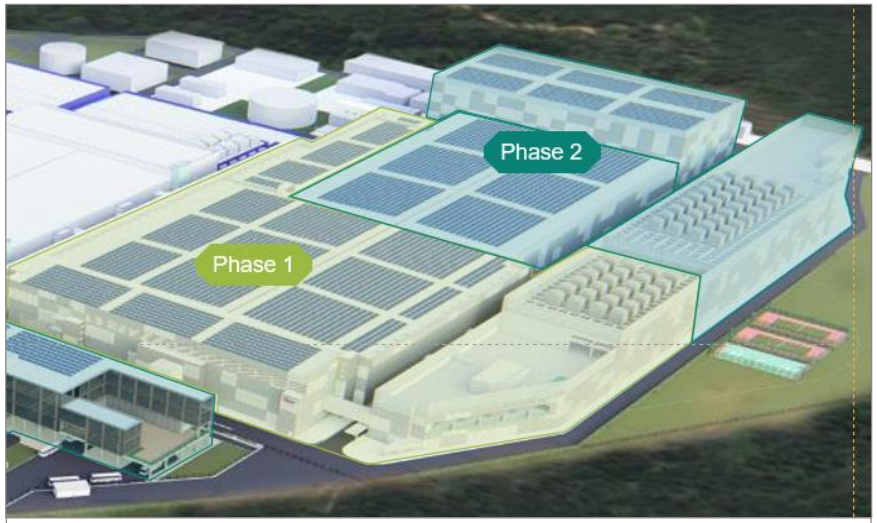
Packaging portfolio

- Best-in-class in-house packaging solutions
- .XT technology for highest power density

P2S

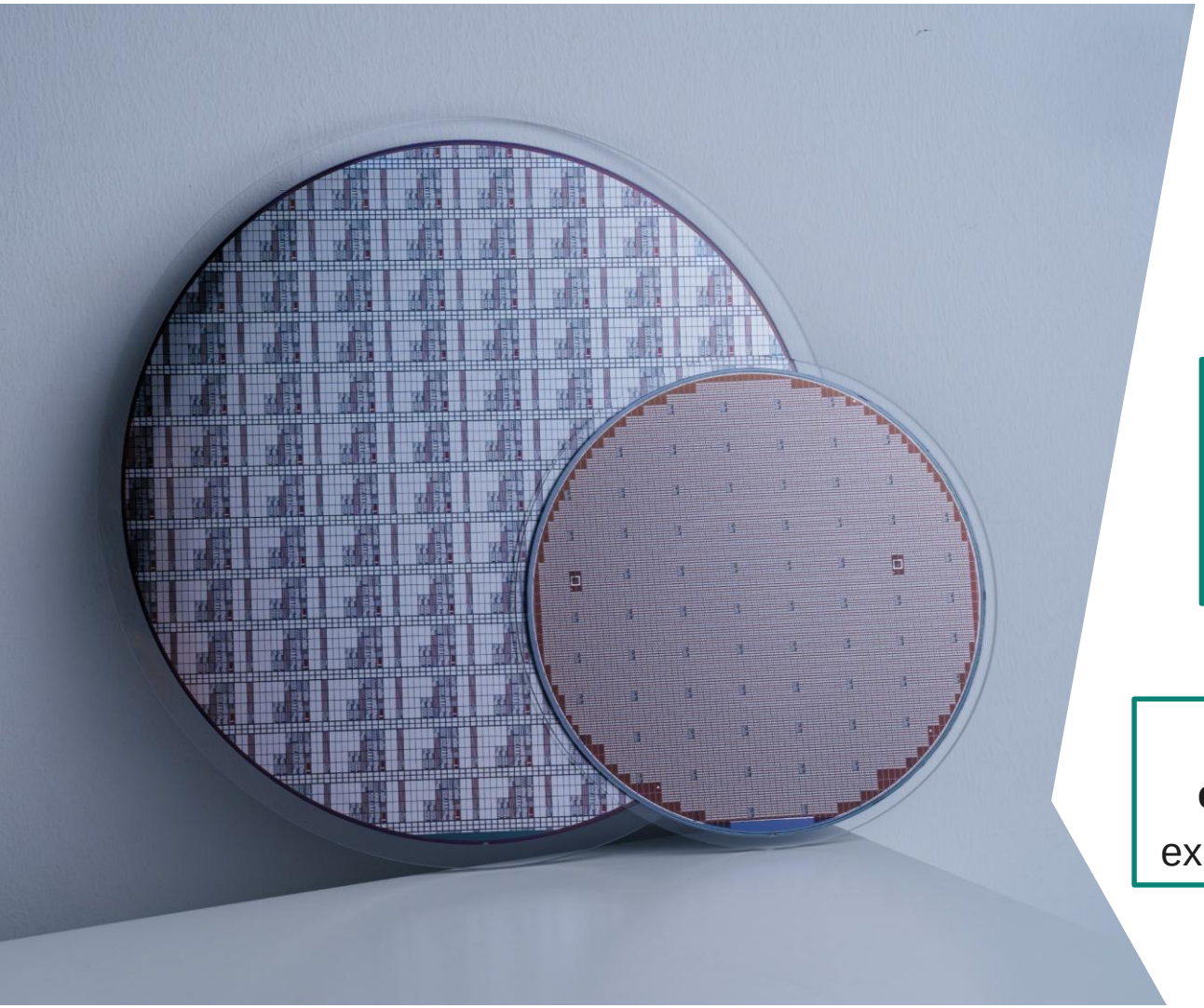
Deep system understanding

- Decades of experience
- Broadest portfolio: off-the-shelf plus customized solutions



Most competitive 200 mm fab with industry-leading cost position.
Resilient setup together with Villach plant

Infineon is a leader in GaN technology and can build on the industry's broadest IP portfolio and application expertise



Broadest IP portfolio in the market (~350 patent families)

Leading GaN product portfolio MV and HV applications

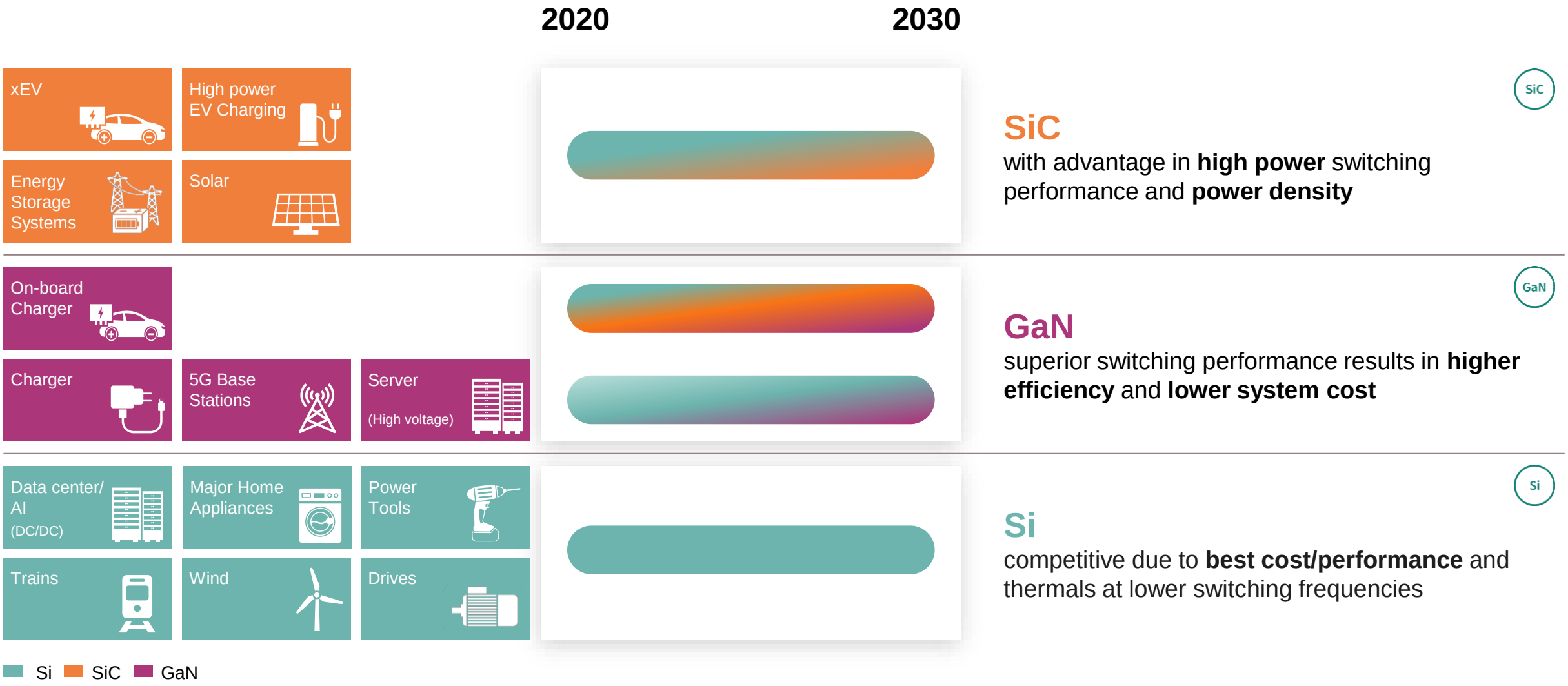
World's first 300 mm GaN manufacturing process strengthens cost-effectiveness

Leadership in GaN

Proven application expertise with > 400 GaN experts and system know-how

Superior customer supply stability through dual-sourcing and scalability

Transition to WBG vastly differs by application with Si expected to remain technology of choice for many of them



SiC

SiC

with advantage in **high power** switching performance and **power density**

GaN

GaN

superior switching performance results in **higher efficiency** and **lower system cost**

Si

Si

competitive due to **best cost/performance** and thermals at lower switching frequencies

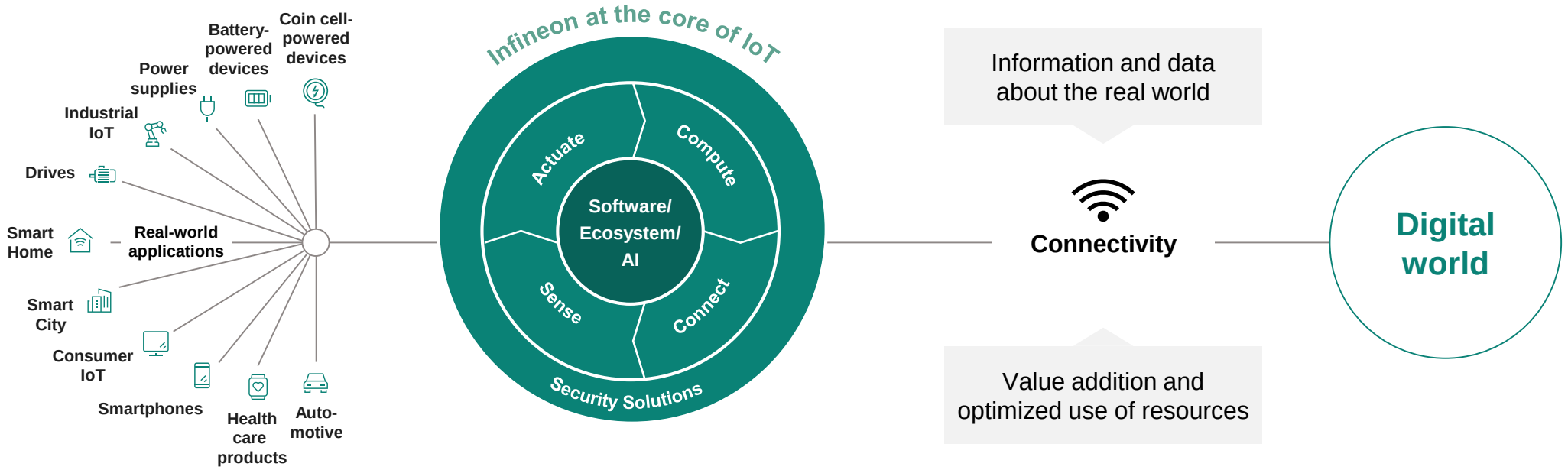
Infineon at the core of IoT – driving digitalization by serving strongly growing multi-application markets

Consumer IoT

Industrial IoT

Automotive IoT

Products: MCU – Connectivity (Wi-Fi, BLE, NFC) – Sensors – Security – Power supply & switches



ESG:
Targets and achievements

Important milestone achieved: The Science Based Targets initiative (SBTi) has approved our CO_2 emission reduction targets

SBTi validation of Infineon's 2030 CO2 reduction targets marks a major step in our decarbonization journey

- **Scope 1 and 2 targets align with the Paris Agreement, limiting global warming to 1.5°C**
  - Specifically, Infineon has committed towards SBTi to **reduce** absolute Scope 1 and 2 greenhouse gas (GHG) emissions by 72.5% by 2030 versus the base year 2019.
- **New Scope 3 commitment**: 72.5% of supplier emissions to be covered by science-based targets by 2029.
- **Key reduction measures** include green electricity, energy efficiency, and voluntary GHG abatement.
- Infineon remains **committed to 100% CO_2 neutrality** goal in Scope 1 and 2 by 2030, as announced back in 2020
  - This will include compensation for the smaller part that cannot be reduced

Our 2030 carbon neutrality goal is aligned with the Paris Climate Agreement's 1.5°C target

CO_2 burden[1]

2.7 million tons of CO_2 equivalents

Ratio

~1:53

previously 1:45

CO_2 savings[2]

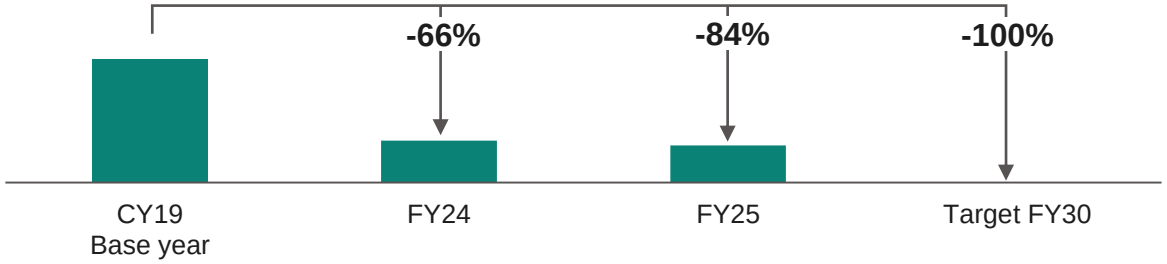
143 million tons of CO_2 equivalents

On the road to carbon neutrality[3] we achieved significant milestones by

– Using green electricity in all our sites

Infineon's CO_2 target[3] by 2025 and 2030

Net CO_2 emissions in million tons of CO_2 equivalents



» Net ecological benefit: **CO_2 emissions reduction of more than 140 million tons**

[1, 2, 3] For further explanation see "ESG footnotes" in the appendix

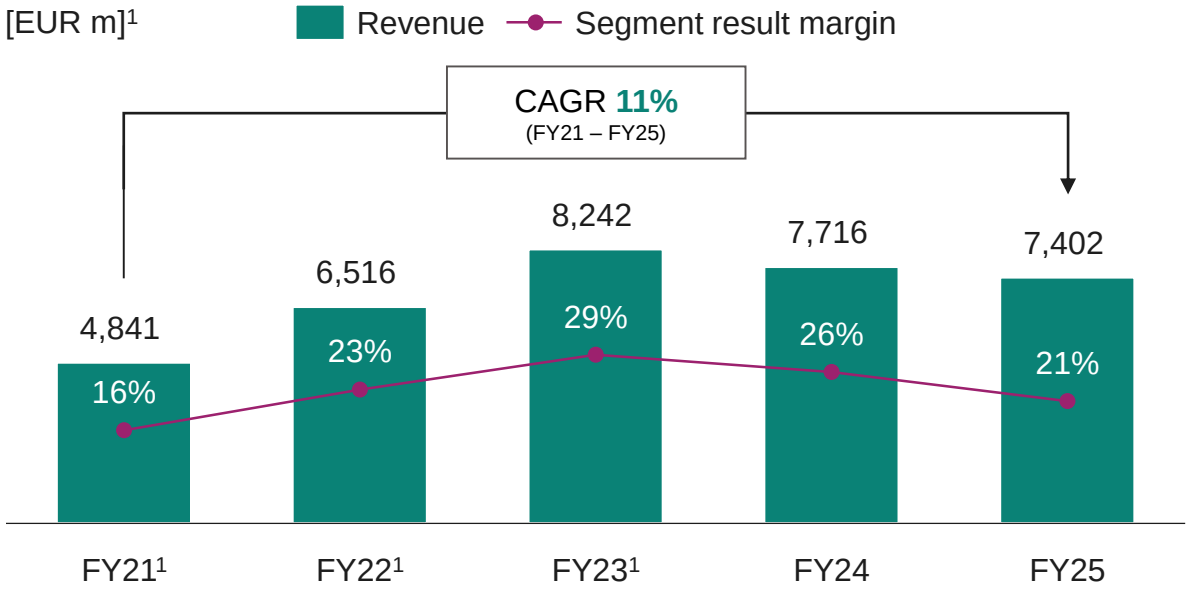
External recognitions confirm our engagement in contributing to a sustainable society

	Rating/Score	Scale	Date
MSCI ESG	AAA	CCC to AAA	05/2025
CDP	B climate scoring B water scoring	F to A	02/2025
Ecovadis	99th percentile “Platinum” award	0 to 100	09/2025
Dow Jones Sustainability™ Index	Dow Jones Sustainability™ World Index listing	-	12/2024
ISS ESG Corporate Rating	Prime Status	-	03/2025
FTSE4Good Index	Index member	-	07/2025
Sustainalytics	ESG industry top performer	-	01/2025

Automotive

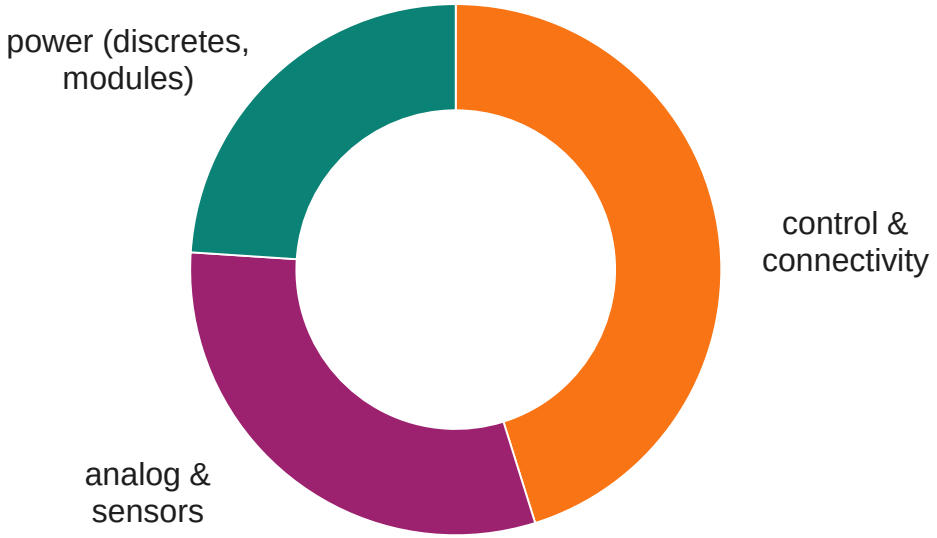
ATV at a glance

ATV revenue and segment result margin



[1] Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

FY25 revenue split by product group

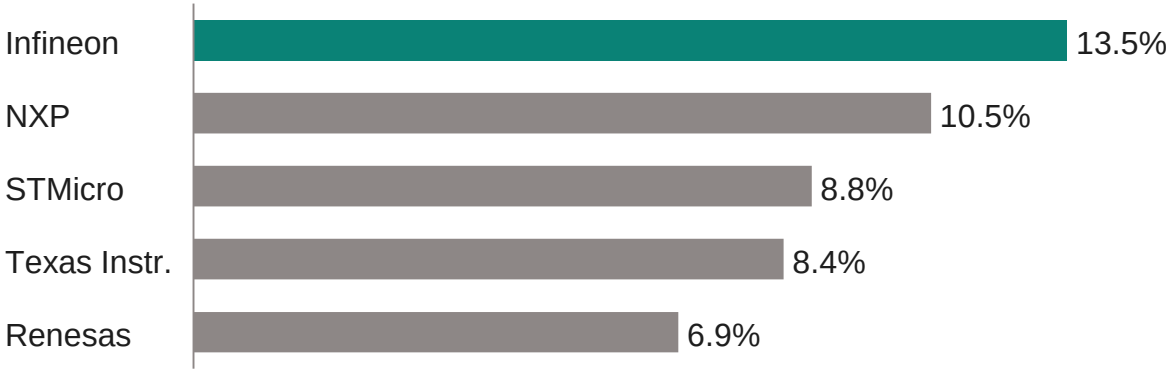


Key customers

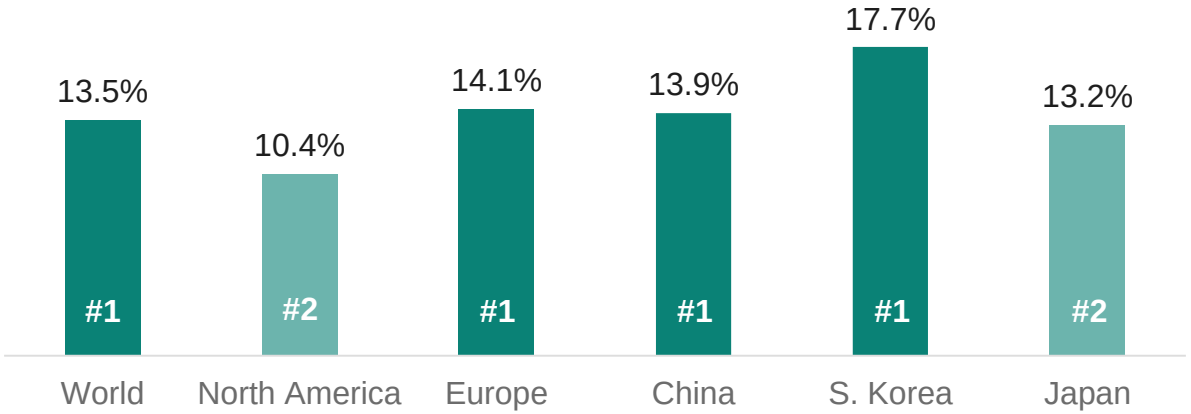
APTIV, Astemo, AUMOVIO, BorgWarner, BOSCH, BYD, DENSO, FORVIA, HYUNDAI MOTOR GROUP, KEBODA, Mando, MAGNA, SCHAEFFLER, Valeo, veoneer, ZF

Infineon's top market position is built on system competence based on an industry-leading product portfolio

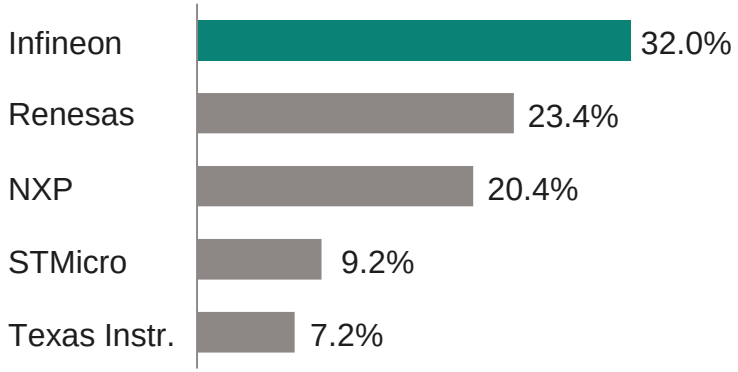
Automotive semiconductors (2024 total market: $68,382m; -1.2% y-y)



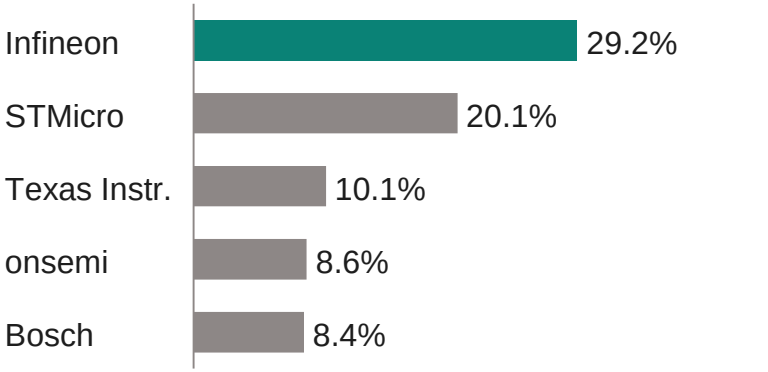
Infineon's 2024 market share and position by region



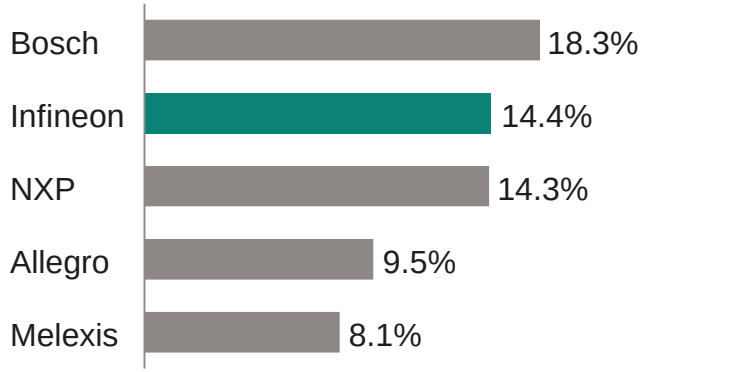
MCUs



Power semiconductors



Sensors



TechInsights: *Automotive Semiconductor Vendor Market Shares*. March 2025. Sensors: S&P Global Mobility: *Automotive Semiconductor Market Share Database.* May 2025.

Several strong content growth drivers for Infineon in xEV and software-defined vehicles, even at flat LV production

Structural trends fueling our growth

xEV

- Strong volume growth of BEVs and PHEVs
- Increasing share of SiC in traction inverters
- More kW per vehicle lead to higher BoM in inverter

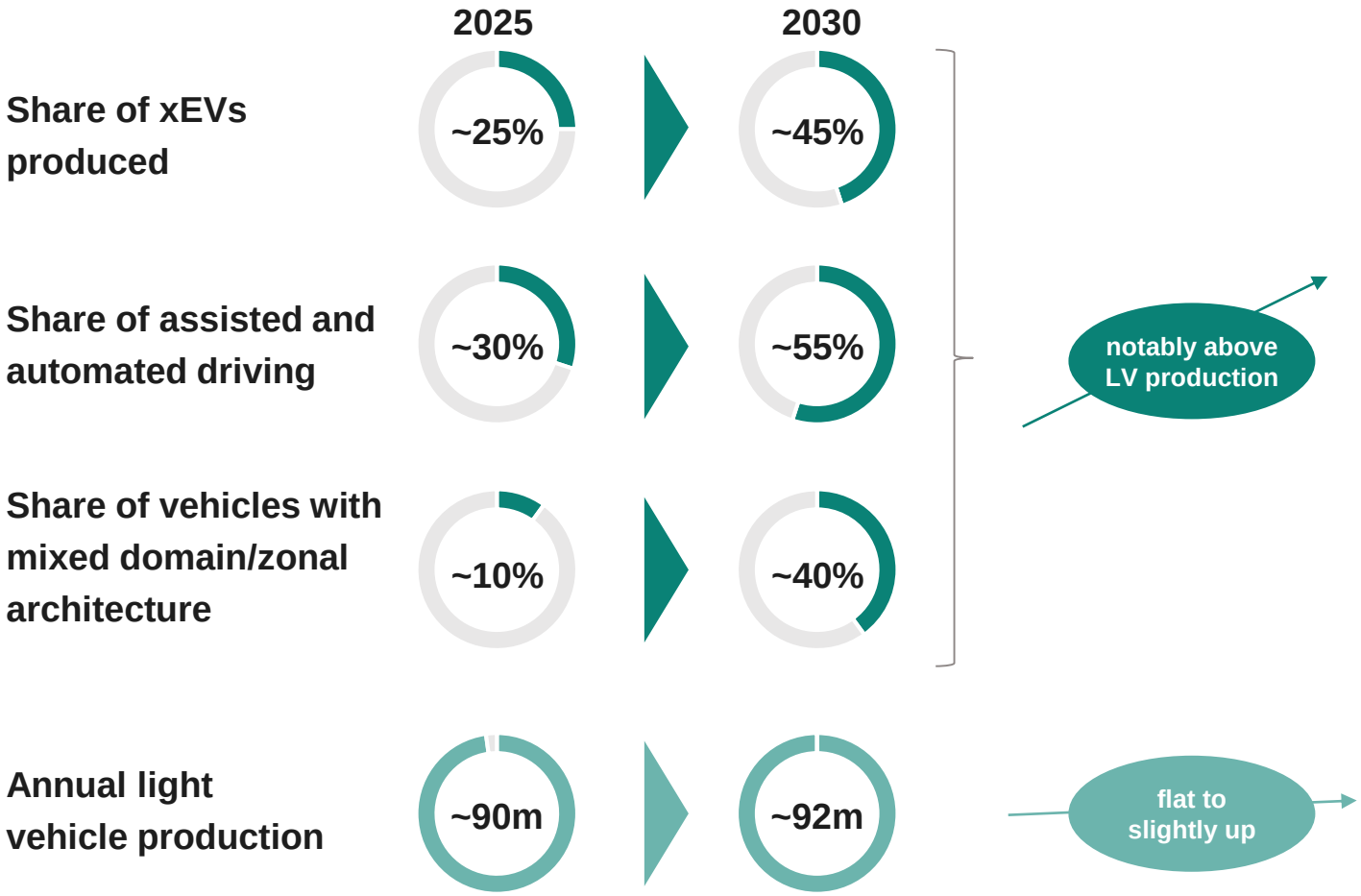
SDV

- Transformation of E/E architecture towards central computing with zonal controllers
- Smart switches for decentralized power distribution
- Software over the air
- Secure connectivity, cybersecurity indispensable
- Functional safety, dependable electronics, redundancy
- ADAS/AD: More sensors, more computing performance

Comfort and premium features

- More loads (motors, heating, cooling etc.)
- More elaborate lighting, both exterior (matrix light) and interior (instruments and ceiling)

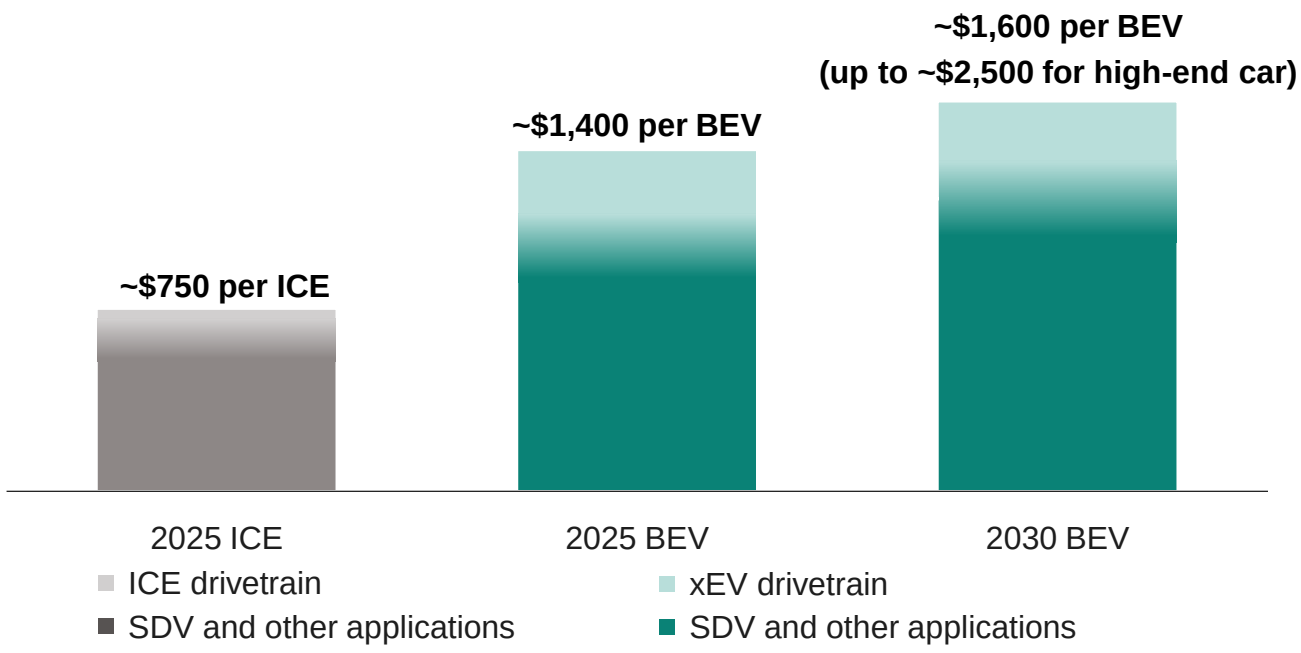
Overview of growth vectors until 2030



Infineon estimates

Infineon is the world leader in automotive semis, serving all key applications and benefiting strongly from content growth

Average semiconductor bill-of-material per car in 2025 and 2030



BEV market size growth (vehicle production)

Semiconductors covered by Infineon

Drivetrain applications:

- Traction inverter, OBC, DC-DC, BMS, auxiliaries
- Drivers for BoM increase:
  - SiC and GaN replacing Si
  - more motors and stronger motors per car
    → slight increase in kW per car

SDV and other non-drivetrain applications:

- Domain/Zone
- SDV, incl. E/E architecture and ADAS
- Safety and advanced security
- Comfort and premium
- Connectivity and infotainment

With a growing xEV market and growing non-drivetrain BoM, Infineon profits twice

Infineon estimate based on S&P E/E & Semiconductor Service dataset – October 2025; November 2025

Number of power MOSFETs per car continues to increase, and drives accelerated growth for the leading portfolio

Examples of MOSFET applications

- Power door
- Power lift gate
- Brake booster
- Electric power steering
- HV-LV DC-DC conversion
- BMS
- Transmission control
- Windshield wiper
- Electric parking brake
- HVAC blower
- Sunroof
- Side mirror
- Seat adjustment
- Thermal management
- 12 V battery switch
- Power supply protection

Latest portfolio with constant innovation

Technologies, packages and voltages

- OptiMOS™ 7
- OptiMOS™ 6
- OptiMOS™ 5
- OptiMOS™ T, T2, Gen 12.7

40 V
60 V
80 V
100 V
120 V

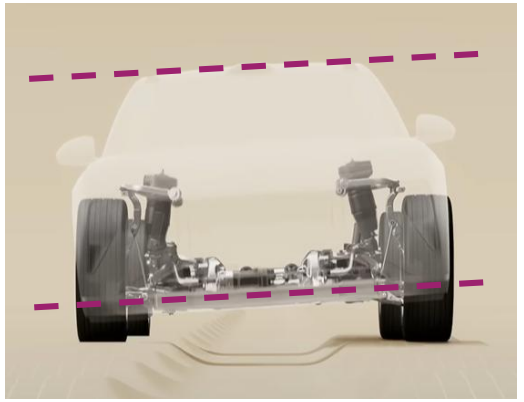
New **OptiMOS™ 7** family with outstanding technical performance

- 100 to 180 MOSFETs are used per vehicle in ~90 different applications in all segments: body, chassis, safety, ADAS/AD, powertrain
- Infineon offers broadest portfolio (>600 products) and eco-system to address specific and high-margin applications:
  - embedded control, gate driver, MOSFETs, software, P2S
  - entire eco-system with digital twins
  - simulation environment (esp. for motor control)

Outstanding electrical characteristics of Infineon products drive innovations, e.g. most advanced active suspension system

World-class active suspension system developed by ClearMotion

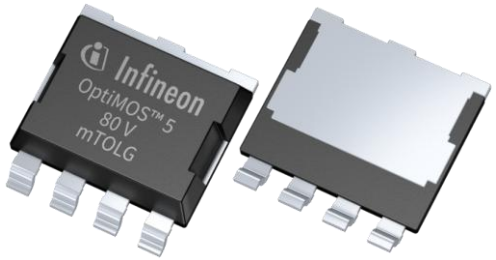
- Designed for 48-Volt high-current application
- Currently featured exclusively in luxury vehicles
- Referred as “flying carpet” for its seamless, flow-like driving experience



passive suspension system

Powered by Infineon’s leading solutions in analog, power, and real-time technologies

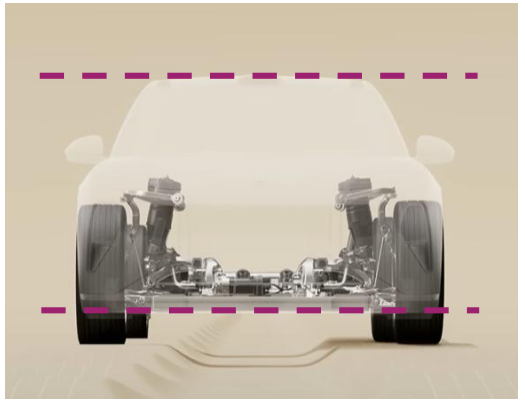
OPTIREG™ PMIC



OptiMOS™ 5, 80 V, 1.2 mΩ

world-class low R_{DSon}

AURIX™ TC366



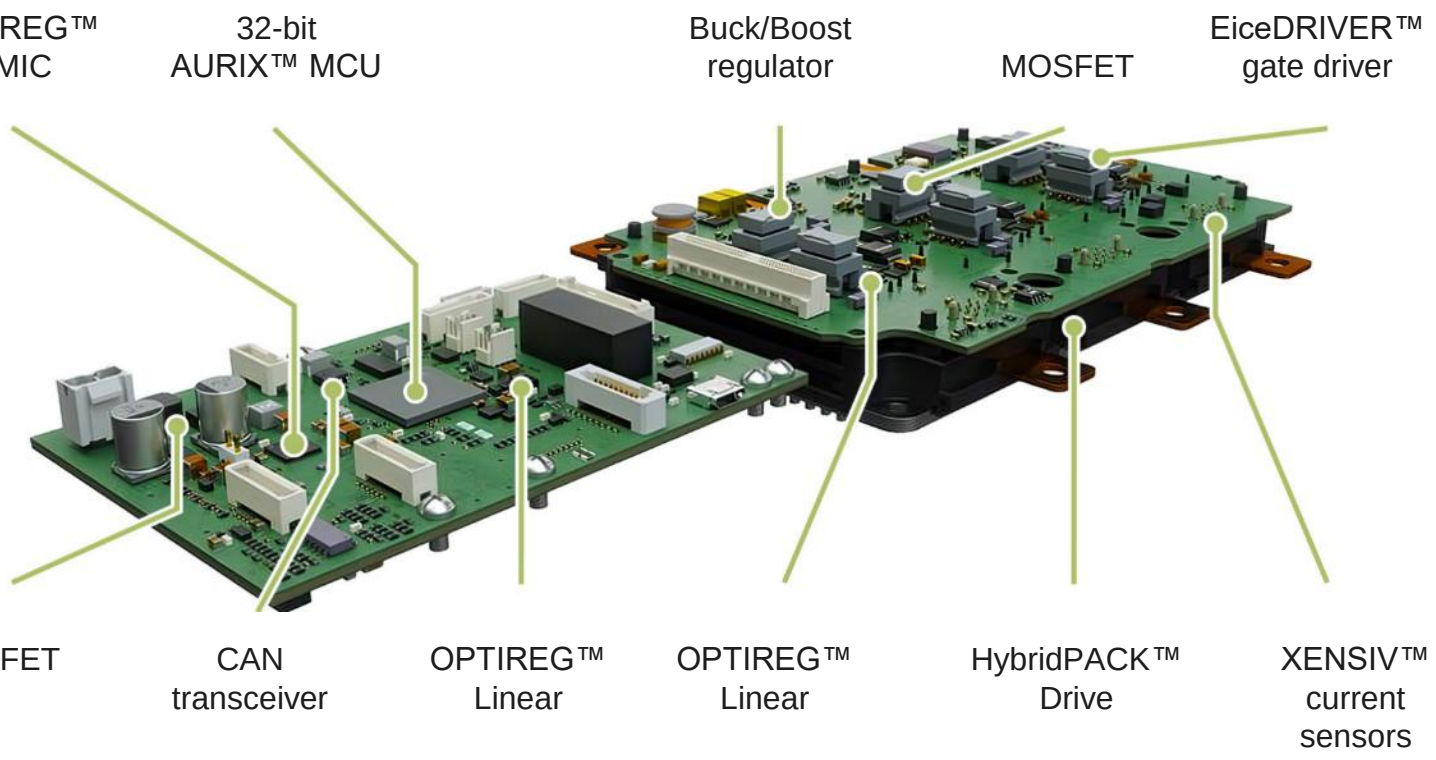
ClearMotion

active suspension system

Electromobility

Infineon’s broad product portfolio and system understanding enable higher BoM and allow compact designs and fast T2M

Infineon inverter reference design, covering up to 95% of value



P2S (product-to-system approach)

- Reference design for up to 300 kW, further customization possible
- System solution for easy implementation
- Fast time-to-market (T2M)

Freedom of choice

- IGBT and SiC in 750/1,200 V scale up to preferred power class
- HybridPACK™ Drive CoolSiC™ Gen2 continuous operation at 175°C
- EiceDRIVER™ gate driver Gen3 optimized for CoolSiC™
- Optimized 32-bit AURIX™ MCU

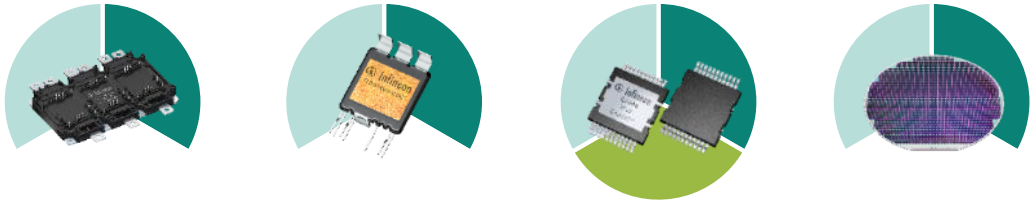
Competitive setup, unmatched portfolio breadth and our worldwide customer base lead to accelerated growth in SiC

Leading SiC technology and production efficiency

- Unrivaled productivity with most competitive fab and most diversified supplier network
- Superior trench technology and highest reliability
- Extensive packaging portfolio and complete system competence

Most scalable SiC auto portfolio

650 V | 750 V | 1,200 V



Module | DSC/SSC module | Discrete | Bare die

Continued strong SiC design-win momentum

BMW, BOSCH, 长安汽车 CHANGAN, CHERY, CHRYSLER, DELTA, FIAT, GENESIS, HYUNDAI, INOVANCE Automotive, JOHN DEERE, KIA, LEAPMOTOR, Lucid, RAM, RIVIAN, SAIC, SCHAEFFLER, smart, STELLANTIS, TOYOTA INDUSTRIES GROUP, Valeo, VINFAST, Volkswagen, Xiaomi, XPENG, ZF

Infineon AURIX™ TC4x with integrated PPU brings AI-on-the-edge to the battery

- **Battery cost**
- **Battery health**
- **Charging speed**
- **Safety concerns**
- **Range anxiety**
- **Resale value, residual value**
- **Cloud dependencies (latency, cost, stability)**

AURIX™ TC4x

PPU
(parallel processing unit)

High computing performance with complex and accurate BMS algorithms

- AI-based battery diagnostic on-the-edge
- temperature model, electro-chemical model
- lithium plating detection
- remaining useful life prediction
- with and without cloud-based updates
- Product-to-System!

Efficient battery cell utilization
- Higher capacity
- Less cells
- Lower battery cost

Faster charging
- Higher user experience

Assure longevity, extended guarantee
- Longer lifetime (in years, in km)
- More charging cycles

Detect and prevent thermal runaway

Accurate battery, health prediction

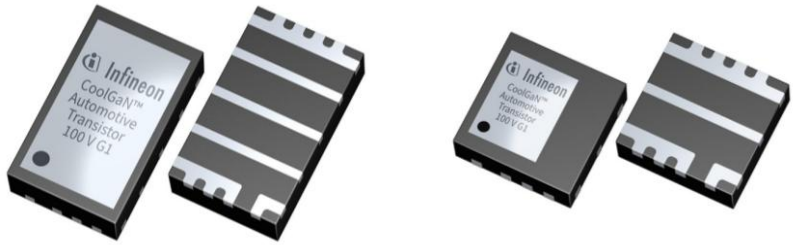
Trust in resale market
- Higher economic value (impacting insurances, fleets, OEMs, Tier1s, 2nd life market)

Open to partner up with further OEMs, Tier1s, insurance companies

Infineon strengthens its leading position in automotive semis – introducing the CoolGaN™ automotive transistor 100 V G1 family

CoolGaN™ automotive transistor 100 V G1 family

- First GaN transistor family qualified to AEC-Q101 for automotive applications
- Features CoolGaN™ transistors and bidirectional switches
- Enables higher energy efficiency and lower system cost
- Combines smaller form factor with higher power density
- Ideal for zone control, main DC-DC converters, high-performance auxiliary systems, and Class D audio amplifiers



Main automotive target applications and the benefits of GaN

On-board charger

HV/LV DC-DC

Higher efficiency: energy savings

Higher power density: less material & smaller size

Lower system cost: more affordable

Traction inverter

48 V/12 V DC-DC

GaN supports new inverter topologies

Efficiency gain (more range or smaller battery)

Power conversion for E/E architecture

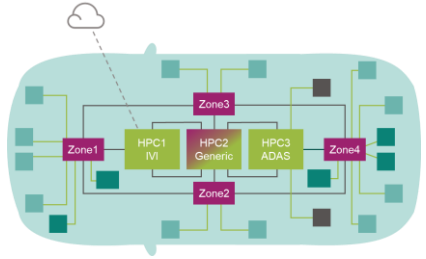
Less material, smaller size, and lower system cost

Software-defined vehicle

Software-defined vehicles are enabled by safe/secure computing, high-speed in-vehicle networks, and intelligent power distribution

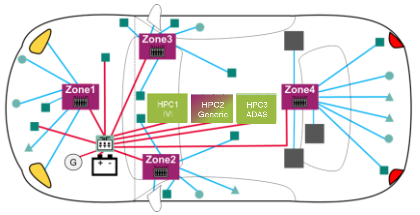
Advantages of software-defined vehicles

- **standardization** of components
- new features in **safety and security**
- **reduced complexity** and **cost** of wire harness
- monetization of **functions & data**
- new features in **comfort**, **connectivity** and **infotainment**
- **digital lifecycle** management



Safe and secure computing and high-speed in-vehicle network

- Evolution to hierarchical/centralized
- Application software decoupled from hardware
- Management of real-time communication in each zone
- **Automotive Ethernet as key differentiator**



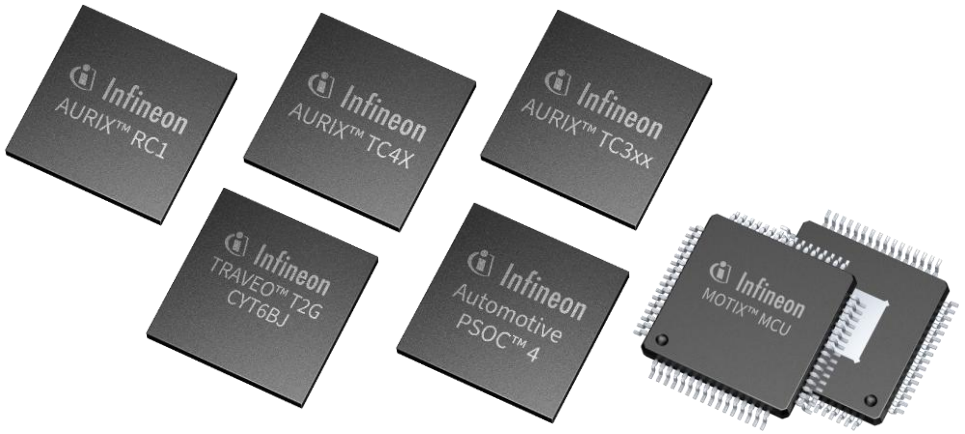
Intelligent power distribution

- Evolution from centralized to decentralized
- Power distribution safety element for
  - freedom from interference
  - system availability up to ASIL-C for ADAS
  - fail-operational of ASIL-D for AD and x-by-wire

The Automotive Ethernet portfolio strengthens our market leading MCU position and increases offering for zonal architectures

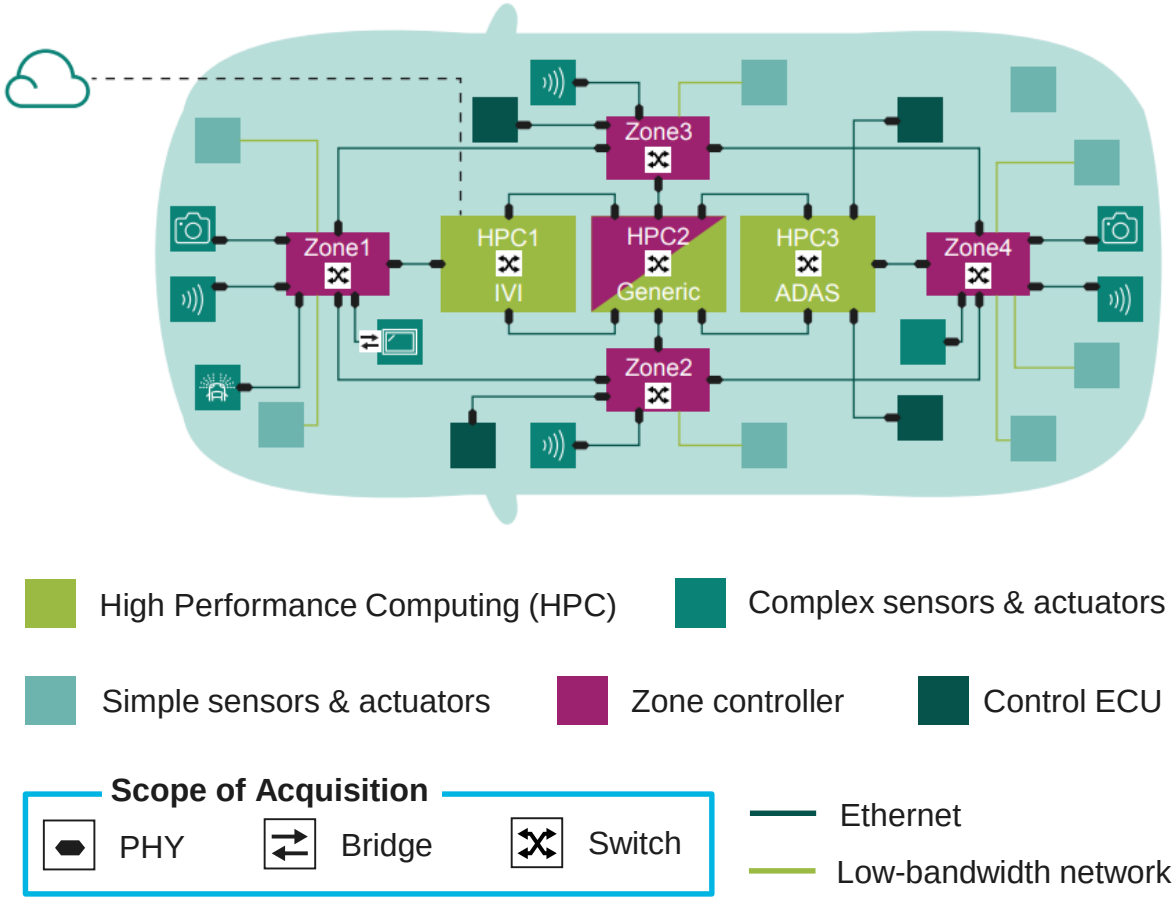
Infineon's unique portfolio of MCU and Ethernet

Automotive MCUs



Automotive Ethernet

Components of hierarchical E/E architectures:



Infineon’s extended portfolio contributes essentially to SDV as the second growth pillar alongside e-mobility

Infineon components for hierarchal computing E/E architecture

Infineon BoM potent.: ~$500

HPC

SoC/MPU | Safety Comp. | Smart Power | Gate Driver | MOSFET | Switch
MPC[1] | PMIC | Memory | Vreg | LIN/CAN Tx | PHY

- High-level control for complex, safe and secured driving functions
- High-bandwidth communication

1-3 units per car
~$45 each

Zone

MCU | Smart Power | Gate Driver | MOSFET | Switch
PMIC | Memory | Vreg | LIN/CAN Tx | PHY

- High-performance real-time control
- I/O aggregation
- Low-latency protocol handling

2-5 units per car
~$50 each

Edge Compute

MCU | Smart Power | Gate Driver | Switch
PMIC | Vreg | MOSFET | PHY

- Low-/medium-performance real-time control
- End-point communication interface
- Direct connection to sensors and actuators
- Sensor data collection and pre-processing

10-20 units per car
~$15 each

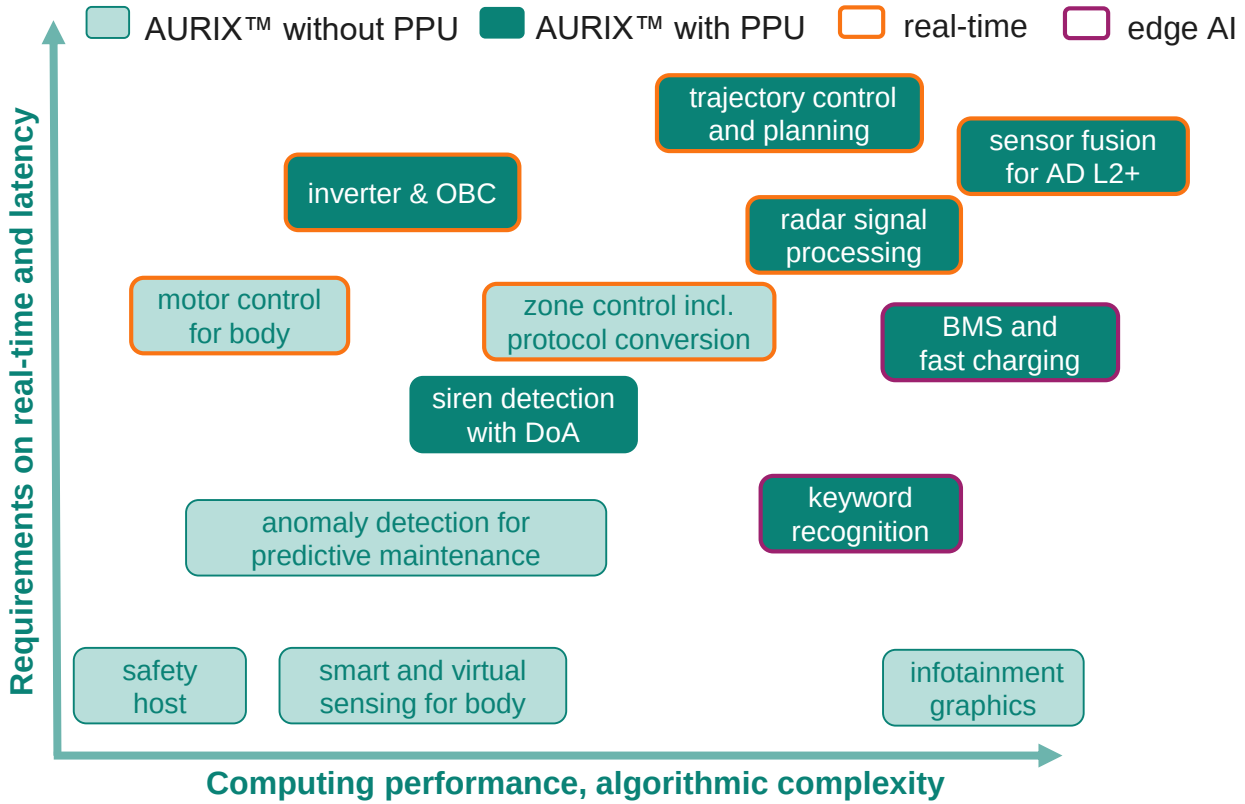
Total BoM for Infineon increases by almost $100 due to Ethernet

[1] Digital multi-phase controller for SoC/MPU

Control | Analog | Memory | Power | Ethernet | Component if needed | Not part of Infineon portfolio

The Infineon AURIX™ family matches ideally all requirements in today's high-end applications

Map of application complexity and latency requirements



TRAVEO™ PSOC™ ARM

AURIX™ TC3 TriCore

AURIX™ TC4 PPU TriCore

AURIX™ Next gen PPU+

PPU (Parallel Processing Unit = a vector DSP co-processor enabling AI on-the-edge up to ASIL-D running at up to 500MHz)

Non-volatile memory up to 24MByte

Dedicated cyber security core

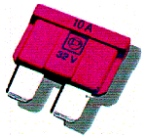
- Most of the real-time and safety-critical applications will not merge into a zone
- TC3 as safety host will remain the gold standard
- Emerging edge AI applications, fostered by imagimob acquisition

imagimob An Infineon Technologies Company

Smart semiconductors in power distribution systems are key enabler for SDV while ensuring high availability and resilience

Infineon PROFET™ Wire Guard enables SDV

Relay replacement



Fuse replacement

Load status diagnostics

Switch

Protect

Diagnose

e.g. PROFET™ Wire Guard

PRO SIL **ISO 26262 compliant**

Fast failure isolation
(< 500 µs)

Central fuse box + many individual ECUs

- Big and heavy
- Complex wire harness
- High power loss
- Risk of interference

Decentral zone ECUs

- Light and small
- Simplified wire harness
- Power efficient
- Freedom from interference
- Design flexibility
- Enable ADAS/AD, x-by-wire

48 V enables higher power demand features for future E/E architectures and automated driving

Demand of in-vehicle loads is sharply increasing and requires 48 V architectures

- More high-power applications and the introduction of zonal E/E architectures drive the need for higher power capabilities
- 12 V power systems are facing challenges
- Future-readiness for automated driving

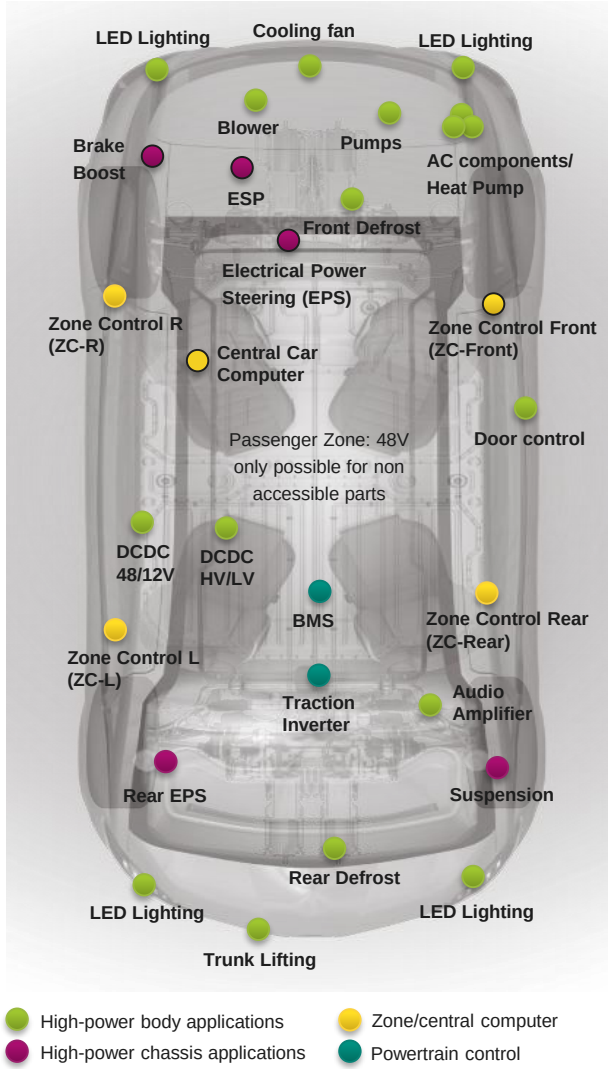
Present high-power features

– Body control	~1 kW
– Chassis control	~1 kW
– Powertrain control	~1 kW
– Cockpit and ADAS control	~0.5 kW
Power demand	**3-4 kW**

around 3x

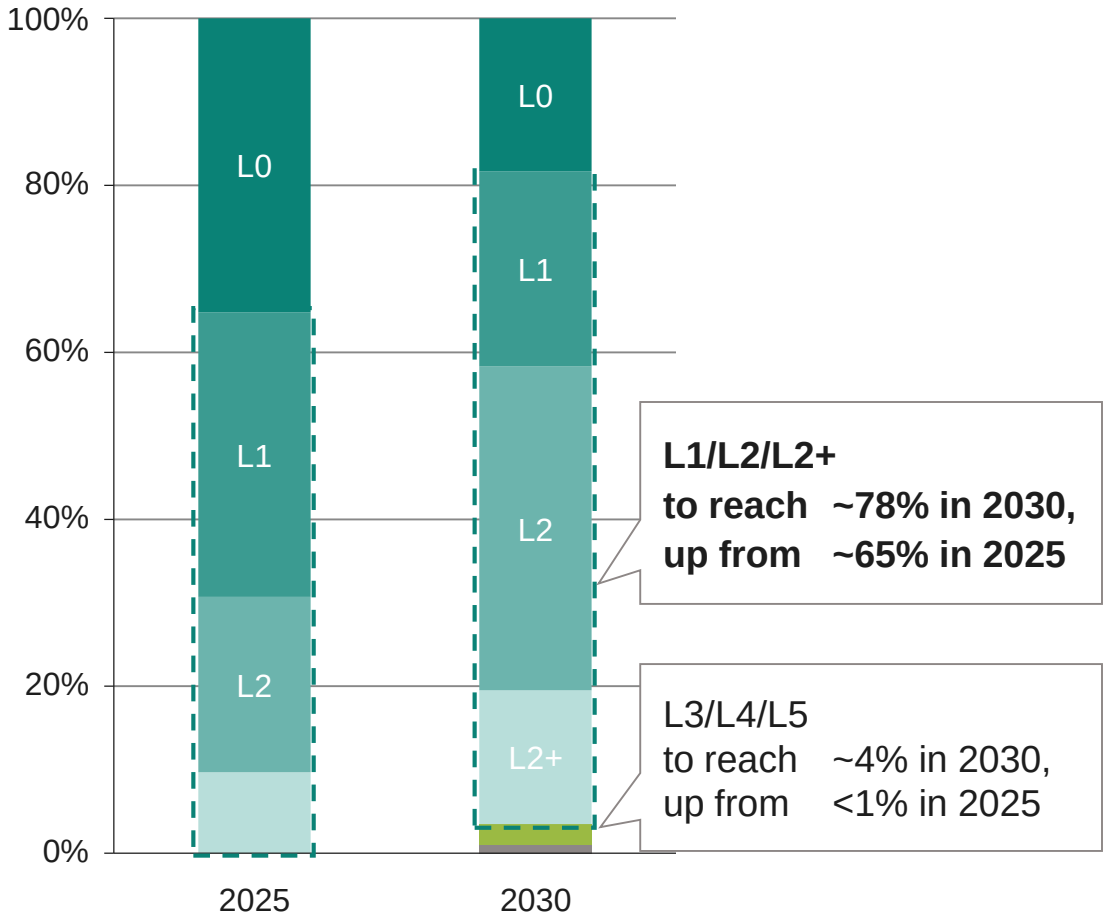
Future high-power features

– Steer-by-wire (EPS)	1-2 kW
– Rear wheel steering	1-1.5 kW
– Brake-by-wire (electro-mechanical brake)	1-2 kW
– Active roll control	~3 kW
– Active suspension	2-3 kW
– Central computer	1-3 kW
– Cockpit (infotainment)	0.5 kW
Power demand	**9-12 kW**

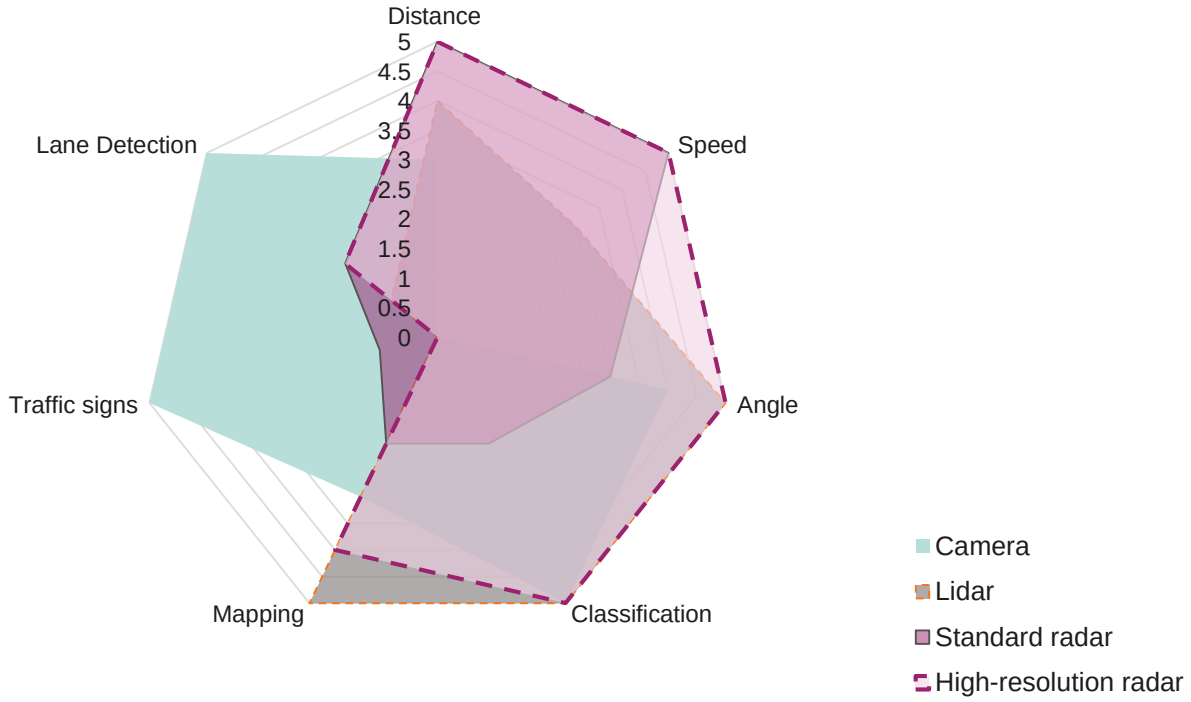


Growth of L1/L2/L2+ is the main driver of ADAS semiconductor content until 2030

Car production by degree of automation (SAE level)



Radar is essential to meet decisive requirements of ADAS/AD



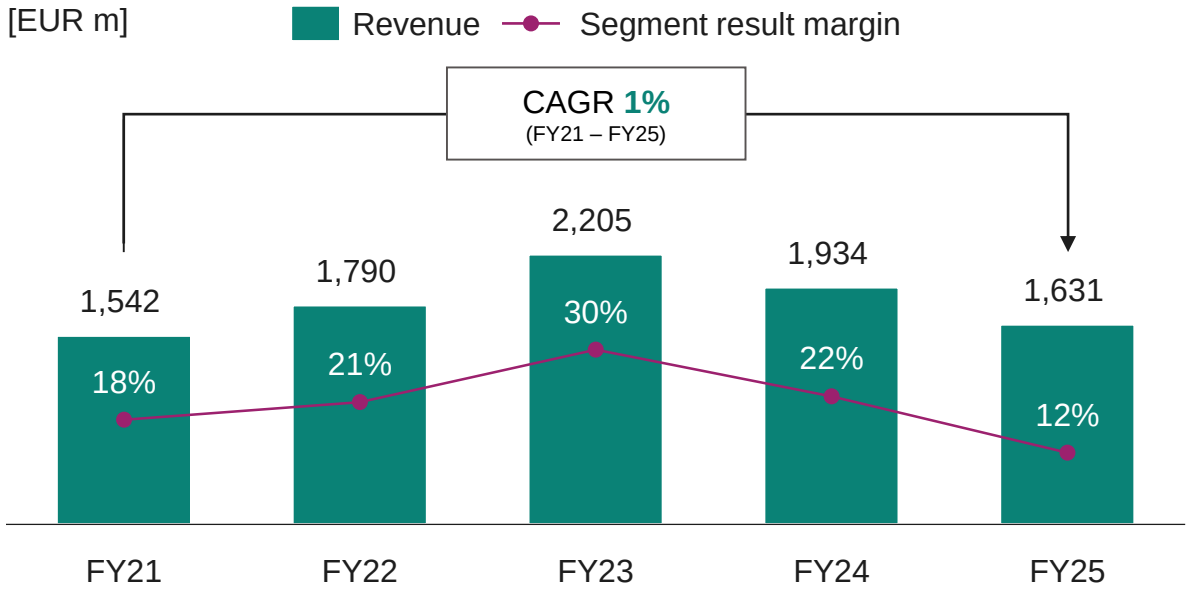
- Standard radar is the technology to detect distance and speed
- High-resolution radar significantly improves angle and classification

Market research companies; Infineon

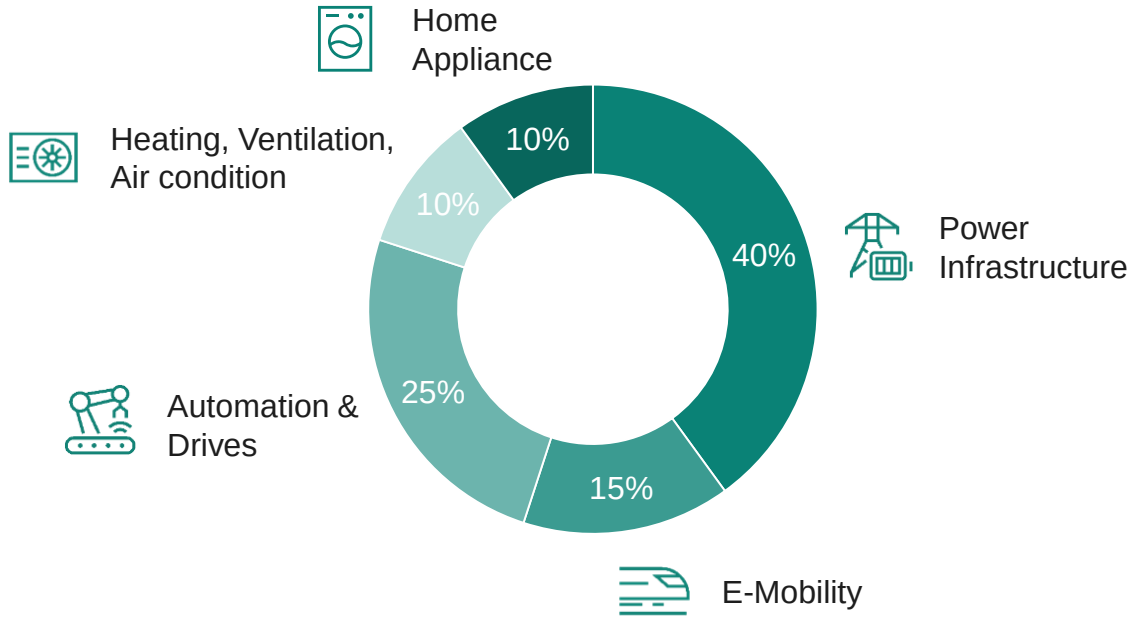
Green Industrial Power

GIP at a glance

GIP revenue and segment result margin



FY25 revenue split by application



Key customers

ABB, Aalpitronic, ALSTOM, Bloomenergy, 中国中车 CRRC, GOLDWIND, INOVANCE, LG, Midea, OMRON, Rockwell Automation, Schneider Electric, SEMIKRON DANFOSS, SIEMENS, SMA, SUNGROW, Vestas, YASKAWA

Huge potential along entire green energy chain until 2030 according to IEA Net Zero scenario

Generation

Photovoltaic	**+4,600 GW**
Wind power	**+1,900 GW**

Infrastructure

Grid network	**$600bn annual investments**
Grid storage	**+900 GW**
EV charging	**+185m chargers (public and private)**
Electrolysis	**+560 GW**

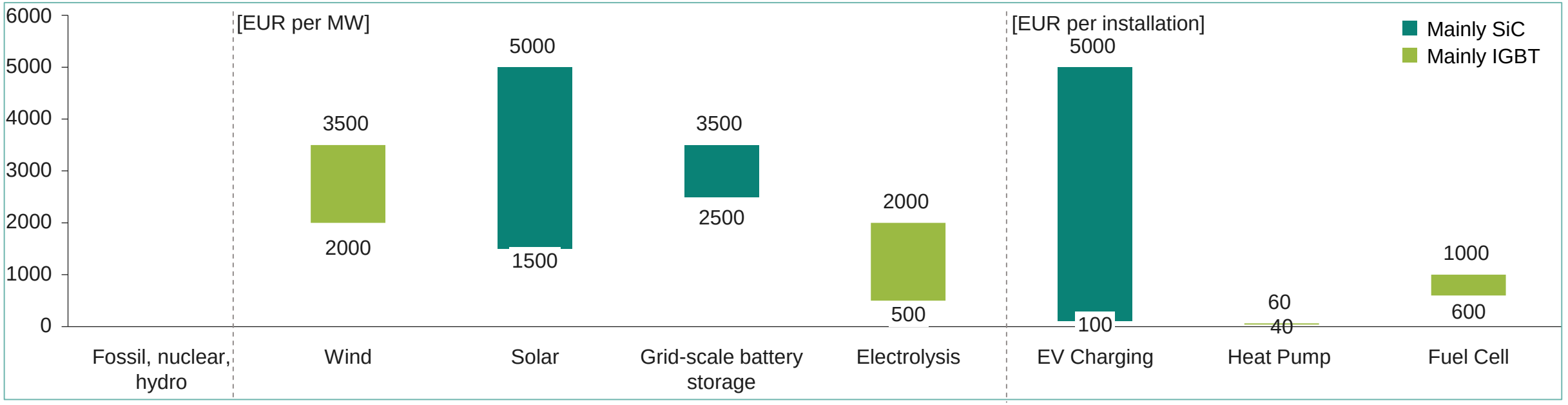
Consumption

Heat pump	**+420m units**
H_2 Fuel cell[1]	**+200k FC EV +200k FC Trucks**
eAviation | eMarine	

Note: Based on Net Zero Scenario (IEA) | Source: IEA - World Energy Outlook, October 2023 [1] Internal Analysis

Green energy generation provides large business opportunities

Power semiconductor content by application

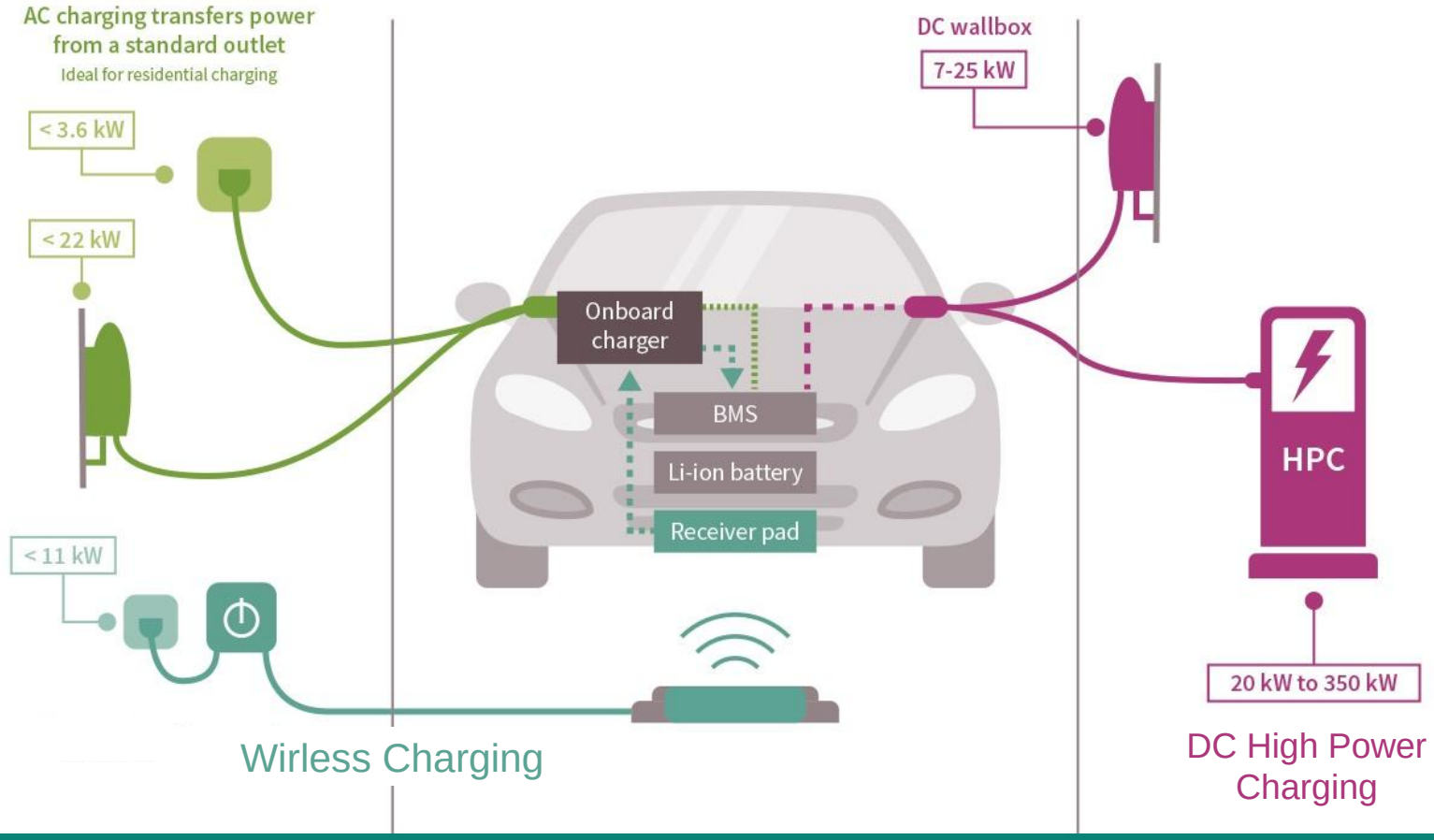


Additions in 2022[1]	**74**[GW]	**220**[GW]	**12**[GW]	**<1**[GW]	**~6m**[inst.]	**22m**[inst.]	**5k**[inst.]
CAGR 2023 – 30	**16%**	**23%**	**56%**	**92%**[2]	**31%**	**16%**	**42%**

[1] IEA: World Energy Outlook, October 2023; Sector Tracking reports October 2023; internal Analysis
[2] Based on 270 GW pipeline (midpoint), >100% based on NZE requirements of 560GW

EV charging is a key strategic application for Infineon
We cover the full ecosystem from AC to high power DC charging

Connectivity solutions	Automotive systems	High power industrial systems

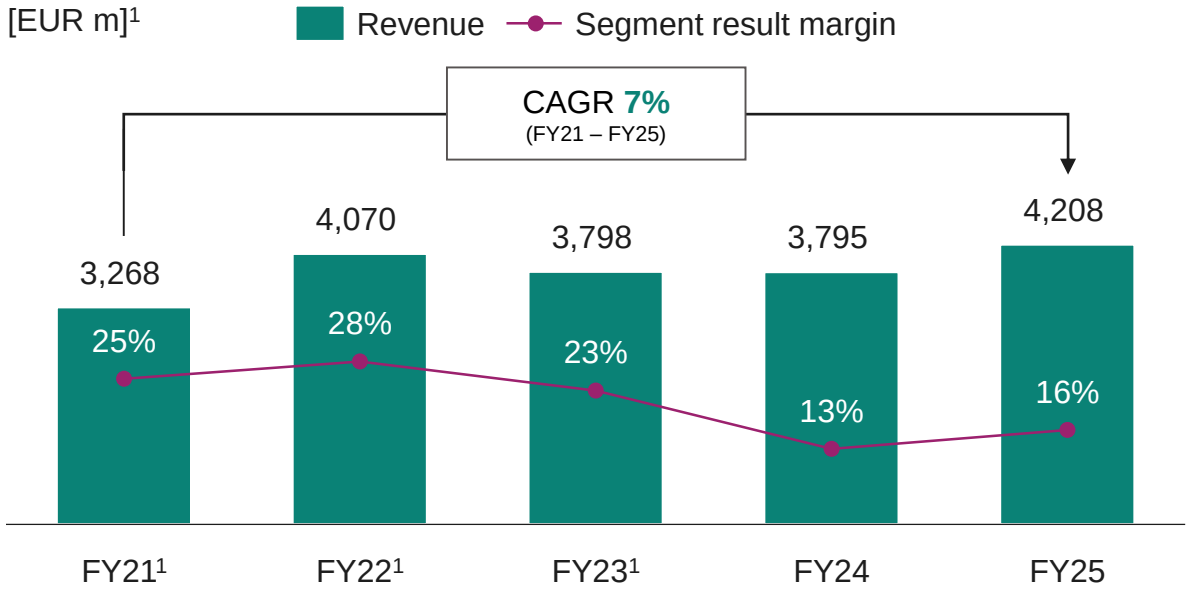


Infineon targets the complete EV charging ecosystem from AC to high-power DC

Power &
Sensor Systems

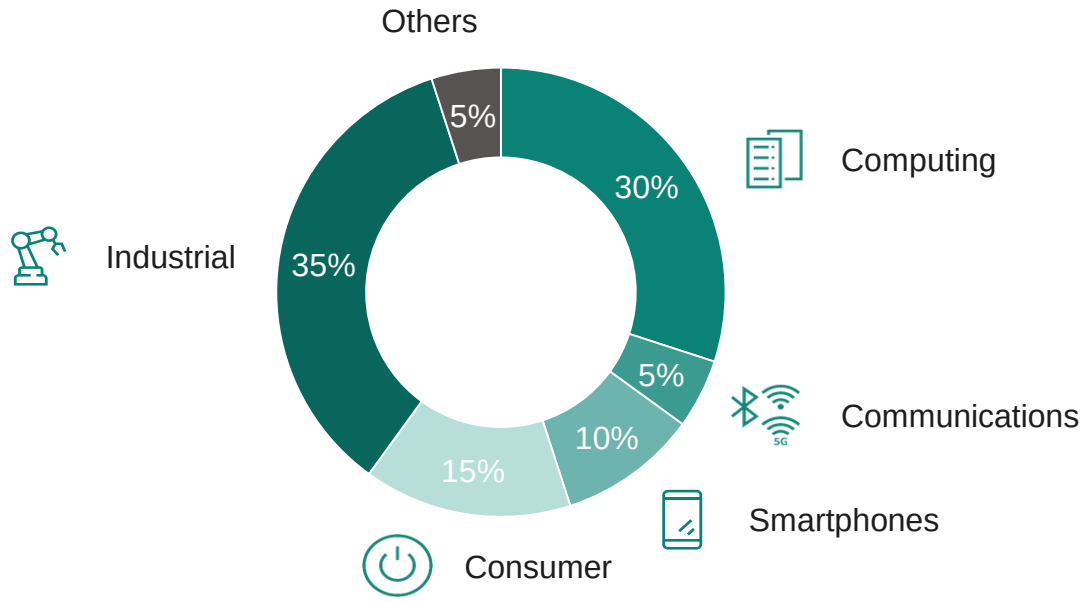
PSS at a glance

PSS revenue and segment result margin



[1] Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

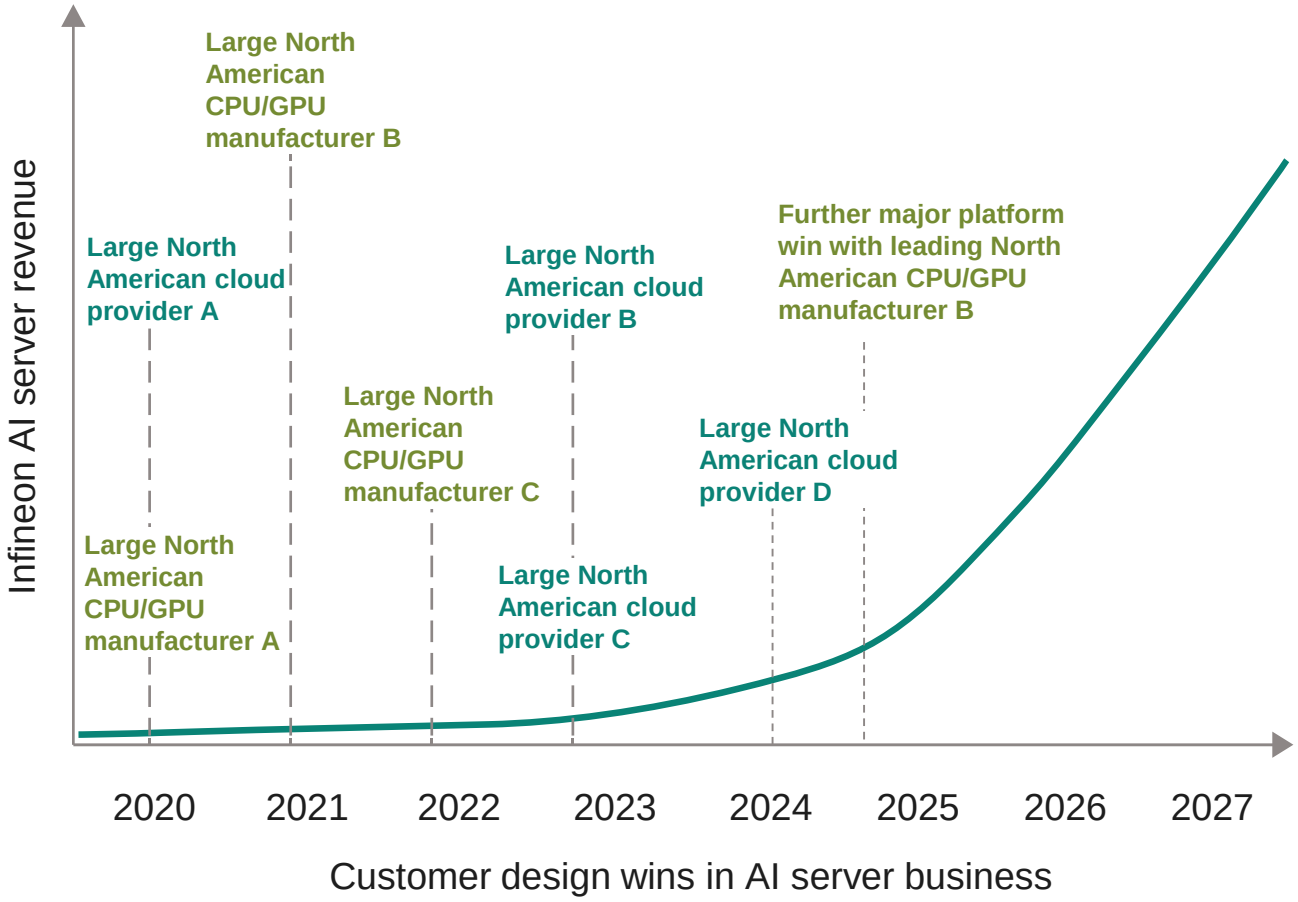
FY25 revenue split by application



Key customers

amazon | cisco | DELL | DELTA | ERICSSON | ENPHASE | Google
hp | LITEON | Makita | Panasonic | SAMSUNG | solaredge | ZTE

AI will be a strong driver of revenue increase for Infineon's server business



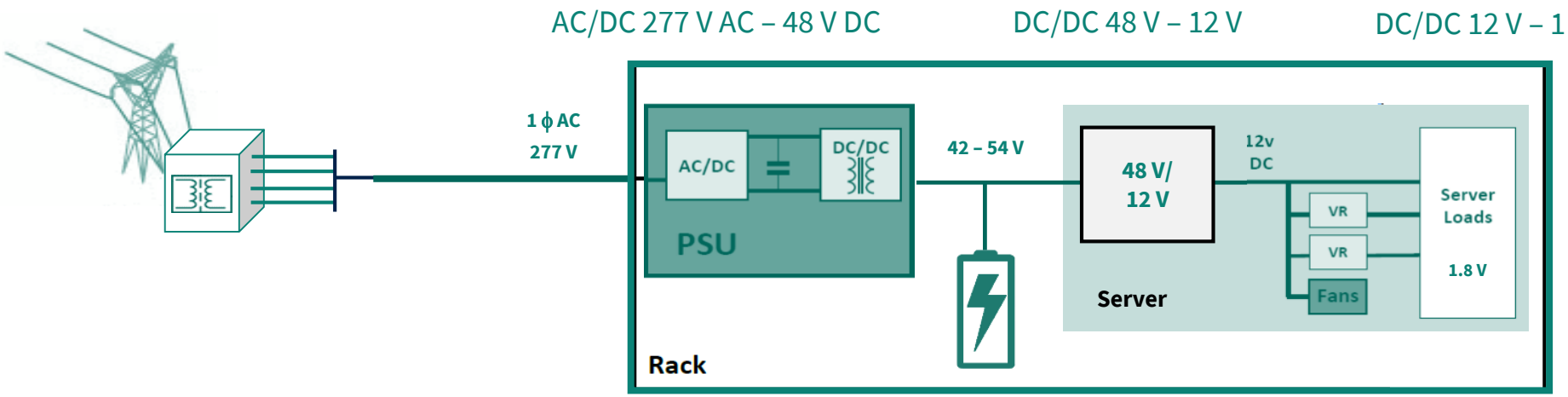
In **FY25**, our AI server business achieved **> €700m** nearly **tripling** vs. FY24

We expect to **more than double** our revenue to **~ €1.5bn** in **FY26**

Addressable market for us **in the range of €8bn to €12bn** by **end of decade**

With its energy efficient power semiconductors Infineon is serving all AI-related power conversion from grid-to-core

Power delivery network losses in an average AI data center



Average data center power flow efficiency today	97%	97.5%	90%	~85%
Efficiency potential from Infineon's leading power semi solutions[1]	98%	98%	94%	**~90%**

[1] Using GaN, SiC & vertical power modules

We power AI – today and in the future
Architectural evolution beyond 250 kW, and up to 1 MW per rack

1

Today

PSUs within server rack

<250 kW/rack

2

2027+

3-Φ HVDC Power Sidecar

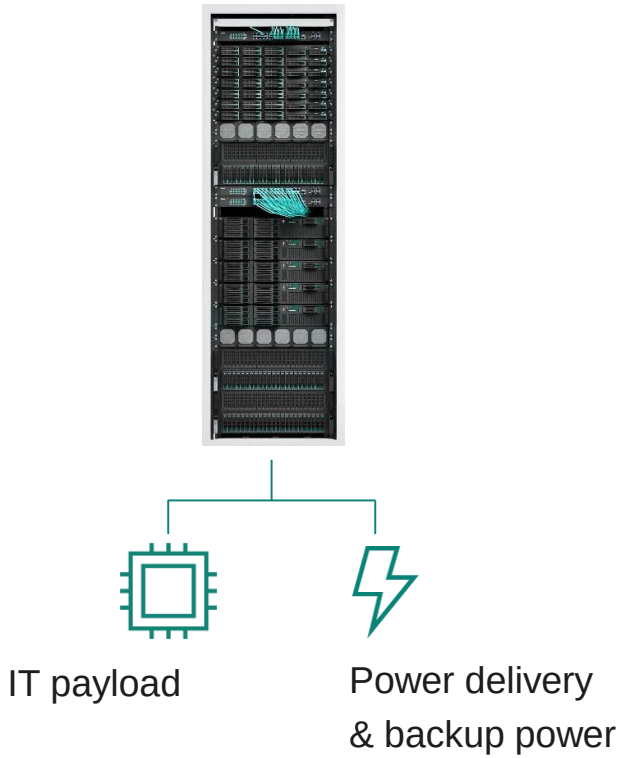
~500 kW+/rack

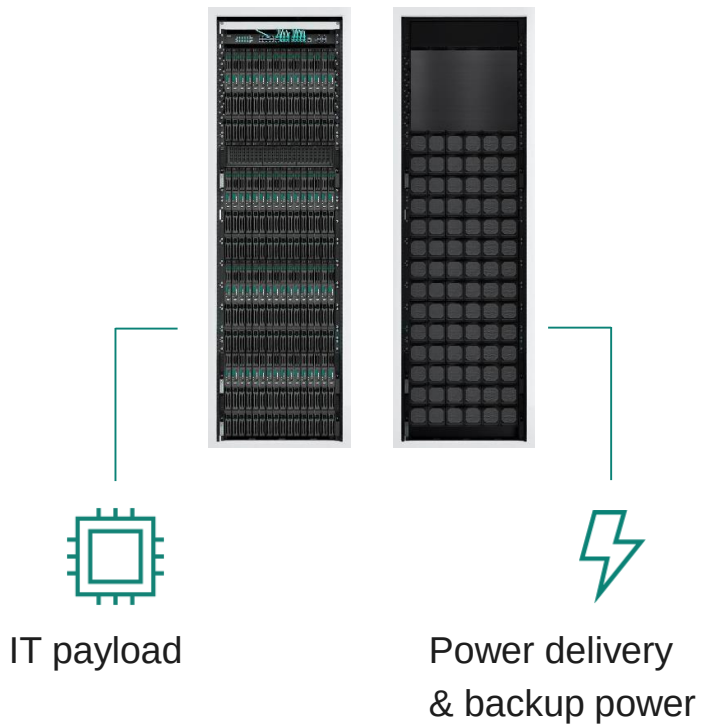
3

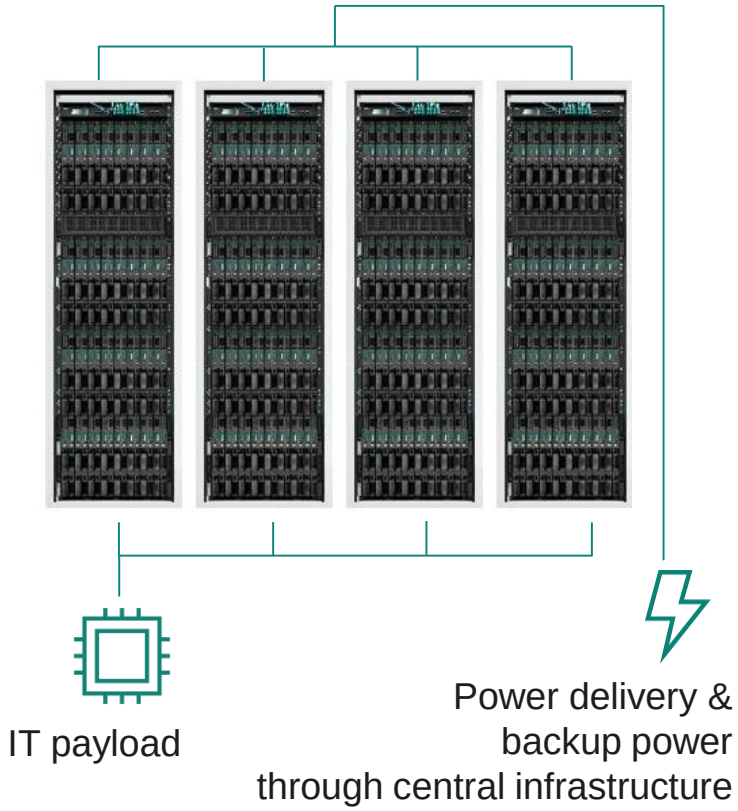
2029+

Hybrid microgrid

1 MW/rack

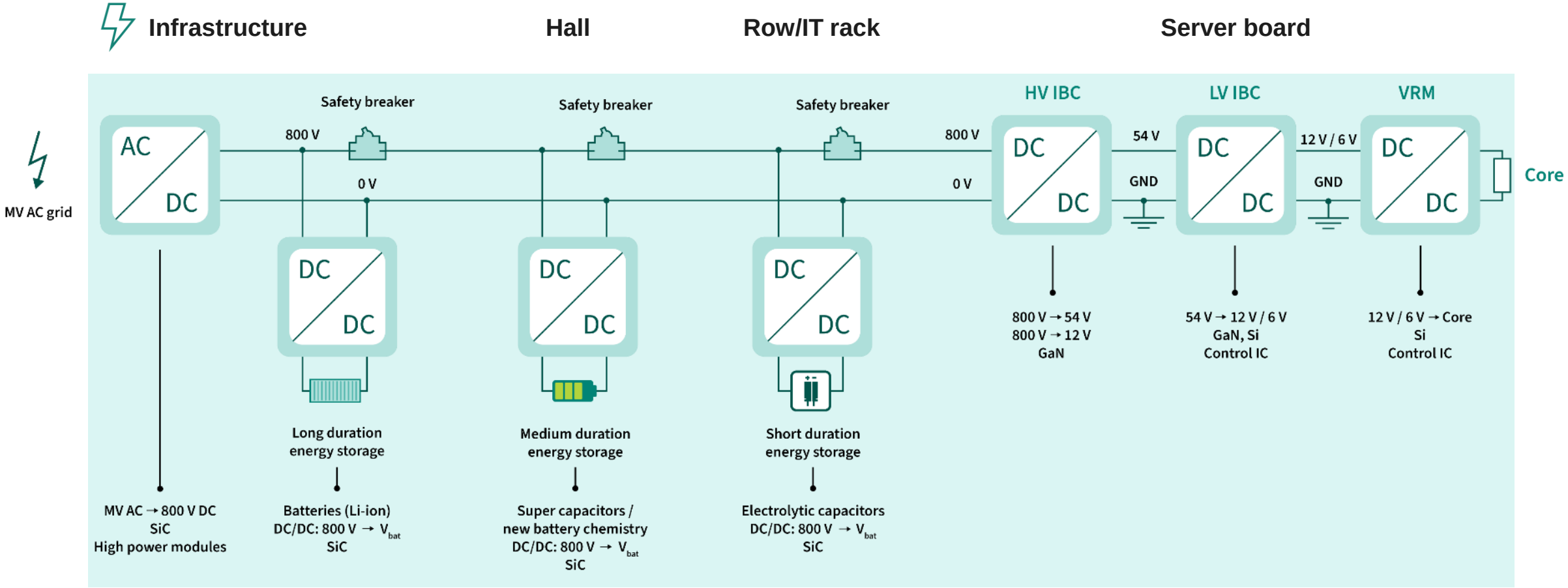




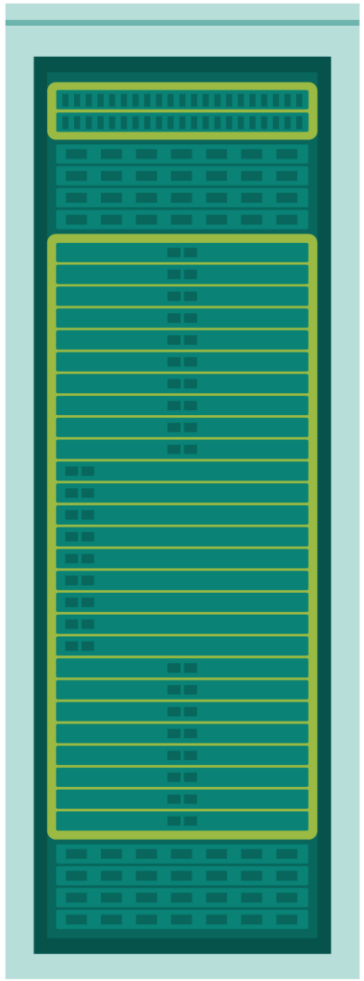


Infineon and NVIDIA collaboration

Future GW-scale data center architecture with centralized power generation using fewest power conversion stages



Leading performance high density AI Server for accelerated compute – Infineon BOM per AI server rack up to between $12k and $15k



Simplified visualization

Top of rack switches
x1 $200-215

PSU (Power Supply Unit)
x24 ~$120

Compute Tray
x10

Switch Tray
x9

Compute Tray
x8

~$120
Either or
~$70

x24
PSU (Power Supply Unit)
BBU (Battery Back-up Unit)

x36
GPU Board
(2 GPU + 1 CPU)
~$130
2nd stage

x18
Power Delivery Board
1st stage
48 V Bus Converter
$70 - $150

x108
Smart Network Interface Cards
~$8

Protection (Hot-swaps, eFuses)
x >300 ~$3

Power System Reliability Modeling possible on every controller

Infineon is tackling the rising power requirements of AI systems with its state-of-the-art PSU solutions for AC/DC

Power Supply Unit (PSU) solutions ranging from 3 kW to 12 kW and beyond

3 kW
η 97.5%
32 W/in^3
1-phase
Si SiC

3.3 kW
η 97.4%
98 W/in^3
1-phase
Si SiC GaN

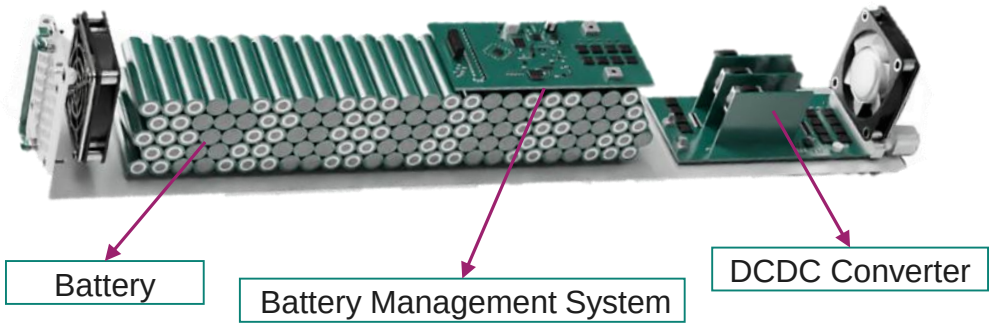
8 kW
η ~97.5%
100 W/in^3
1-phase
Si SiC GaN

12 kW
η ~97.5%
113 W/in^3
1-phase
Si SiC GaN

>12 kW
3-phase
Si SiC GaN

Addressing the Challenge of Increasing Battery Cells with innovative solutions for High Power Density

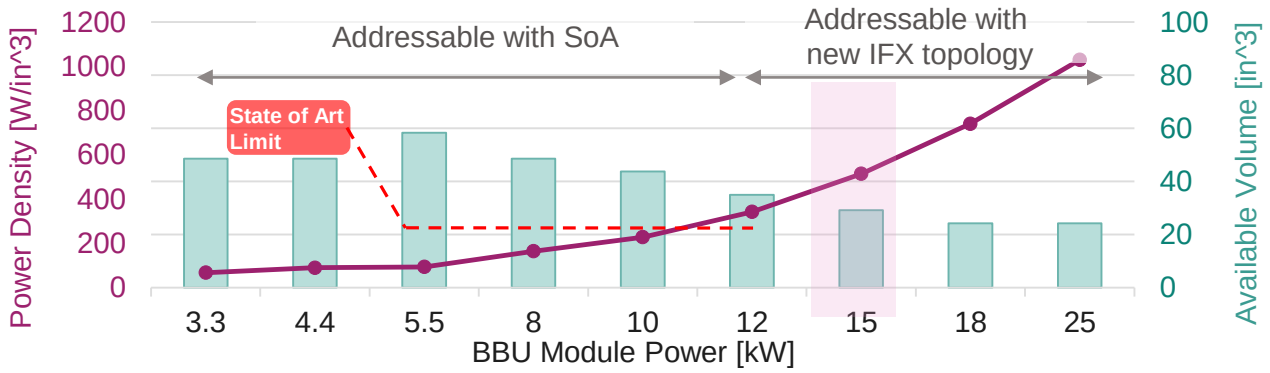
BBU Module Functions



- **Power density x4** higher
- **Efficiency** increase **+1 - 1.5%**
- **Flat efficiency curve**
- **BOM optimization** thanks to the down-sizing of component rating
- **Unparalleled power density and efficiency** by harnessing the potential of **GaN technology**

1. **Converter Power Density** to **enable more battery cells** per BBU
2. **Protect AI servers** from power fluctuations (peak power shaving)
3. **Prevents data loss** and **system downtime**
4. **Efficiency for TCO[1]** in peak shaving
5. **Thermal Management** in air cooled solutions
6. **Quicker recharge**
7. **Full system** portfolio based on Infineon's **patented topology**

[1] TCO – total cost of ownership



Outperforming existing solutions in terms of efficiency, power density and cost-effectiveness

OptiMOS™ 6 80 V MOSFET in DC-DC converter sets new benchmark for AI server power efficiency in leading AI server platform

Key Facts

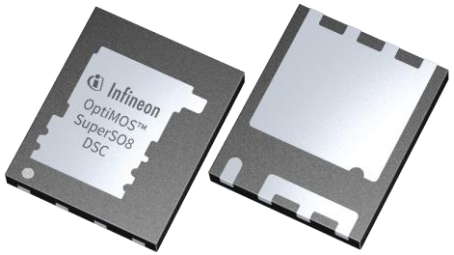
Optimized for 48 V IBCs

Offers **optimized switching performance** in hard switching topologies

Efficiency increase of around 0.4% compared to previously used solutions

Compact package **enables cooling on both sides**

Package



5x6 DSC
5x6 mm² dual side cooling (DSC) package

Applications

Artificial intelligence

Datacom Telecom

SMPS

Server

Evolution of power modules by doubling power density with smaller form factors

Dual-Phase power

TDM2254xD

Discrete Chip Embedded Powerstage
3x die embedded
1.0 A/mm²

2024

Dual-Phase power

TDM2354xD,
TDM2354xT

Substrate Chip Embedded Powerstage
6x die embedded
1.5 A/mm²

2025

Quad-Phase power

TDM24545S

Substrate Chip Embedded Powerstage
12x die embedded
2.0 A/mm²

2025

Pushing power density envelope without compromising thermal performance

- High efficiency achieved using proprietary magnetics
- Chip Embedding enables enhanced thermals

AI

- Quad-phase module has embedded input and output capacitors (>400 µF)
- Quad-phase module enables True Vertical Power Delivery

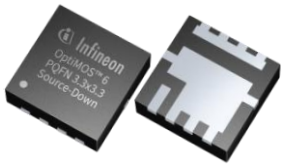
Vertical power delivery reduces power losses in AI data centers

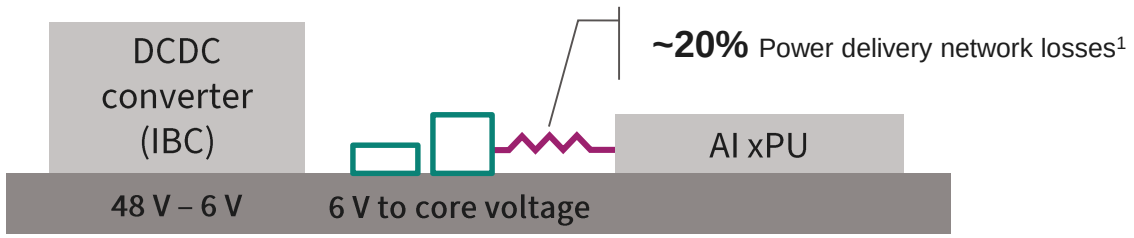
Why backside mounting of our ultra-high current density power module?

~85% Reduction of power delivery network losses compared to lateral “down” solution

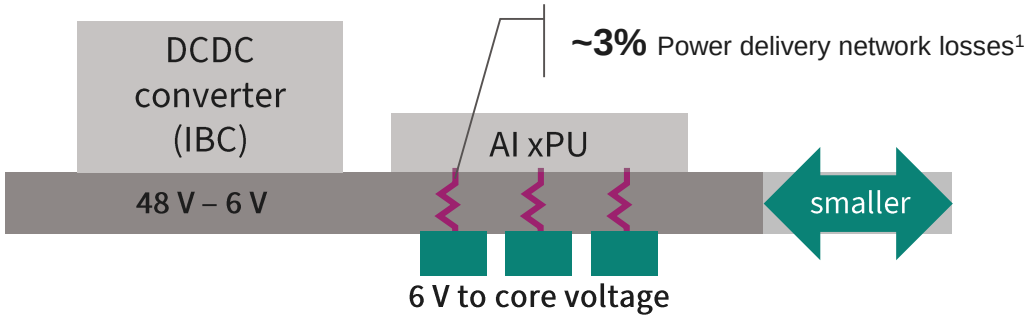
~55% Reduction in size compared to lateral “down” solution

Lateral power delivery
of a discrete "down" solution





Vertical power delivery
of our ultra-high current density power module



Infineon discrete "down" solution Infineon power module solution Resistance Motherboard

Source: Infineon calculation with TDA245C0 and TDM24545S quad-phase power modules

[1] Power Delivery Network (PDN) loss in % of xPU power

Sensor business in one organization will create clear benefits for the customers as 3rd pillar besides Power & Embedded Control

Infineon joins forces to become a leader in the sensor market

Customer centricity

Strengthen go-to-market approach

Faster time-to-market

Comprehensive portfolio

Combined roadmap for innovation leadership

Leverage synergies

Innovation-to-customer

Shared and broad customer support

More customer value

PSS Business Unit SURF (Sensor Units & RF)

PSS Business Line
Radio Frequency & Sensors

RF | Ambient Sensing | MEMS

ATV Business Line
Sense & Control

MEMS | Magnetics | Radar

Consolidated product portfolio with broad applications

Automotive

Industrial

Consumer

Magnetic Sensors			MEMS				RF	
Speed	Current	Position	Pressure	Gas	Sound	Innovation	Radar 3D-Imaging	Mobile & Wireless RF

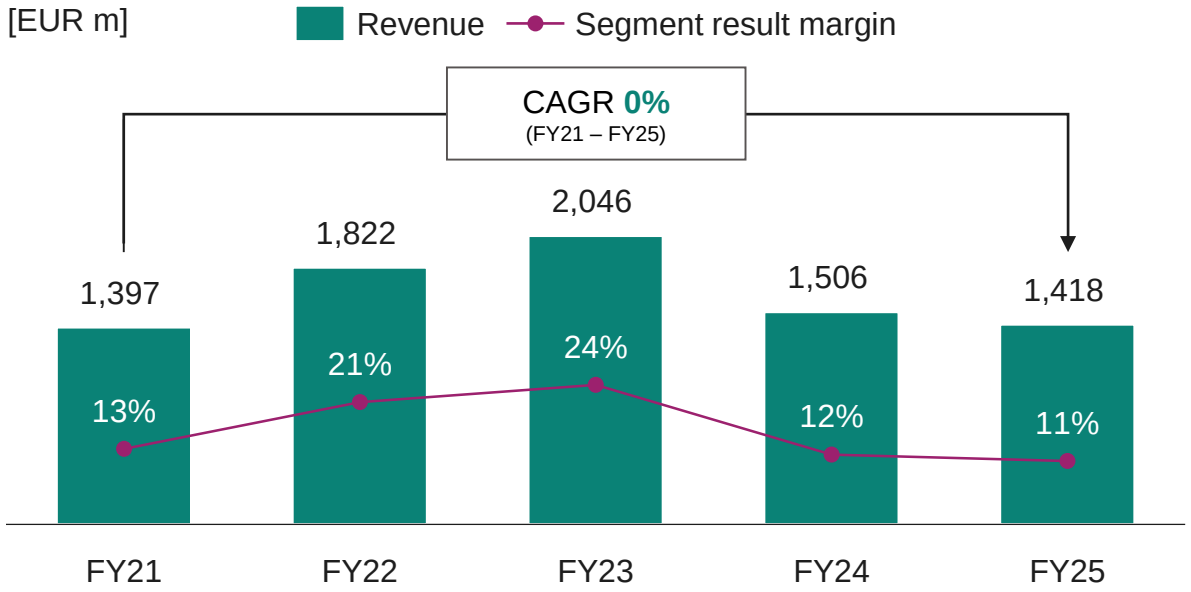
Infineon SURF serves all markets even better

- Efficiency gains by leveraging synergies
  - Short term: more sensor holistic business development and support
  - Mid- to long term: stronger product roadmap and go-to-market

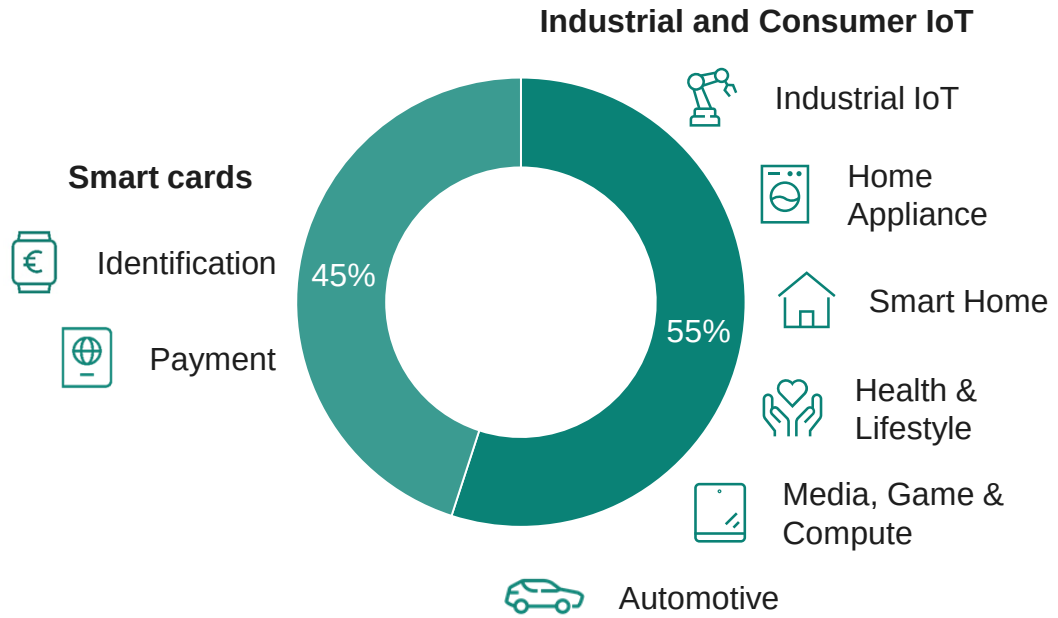
Connected Secure Systems

CSS at a glance

CSS revenue and segment result margin



FY25 revenue split by application



Key customers

AdvanIDe, amazon, arlo, AUSTRIACARD, cpi card group, GPO, Haier, Hisense, hp, IDEMIA, Midea, Nintendo, PERFECT Plastic, Raspberry Pi, SAMSUNG, SONY, THALES

Providing the essential building blocks compute, connectivity, security, and software

Consumer

Industrial

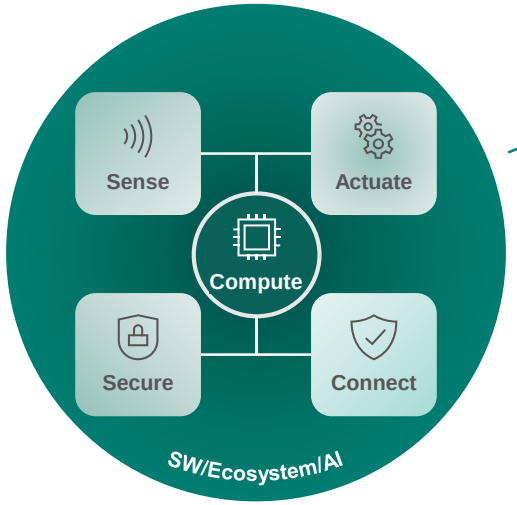
Automotive

Compute

PSOC™ and **XMC™ micro-controllers** allow customers to enable smart, connected products

Software

DEEPCRAFT™ Studio and **ModusToolbox™ software** simplifies and accelerates development for Infineon MCUs



Security

OPTIGA™, SECORA™ and TEGRION™ solutions provide robust embedded security for IoT devices, authentication, payments, identification, and access control

Connectivity

AIROC™ Wi-Fi and **Bluetooth®** products provide ultra-robust, low-power wireless communications

CSS seamlessly interconnects **compute, connectivity, security, and software** - the essential building blocks of digitalization

Infineon's MCUs at the heart of every IoT and Edge AI application

New compelling MCU platforms

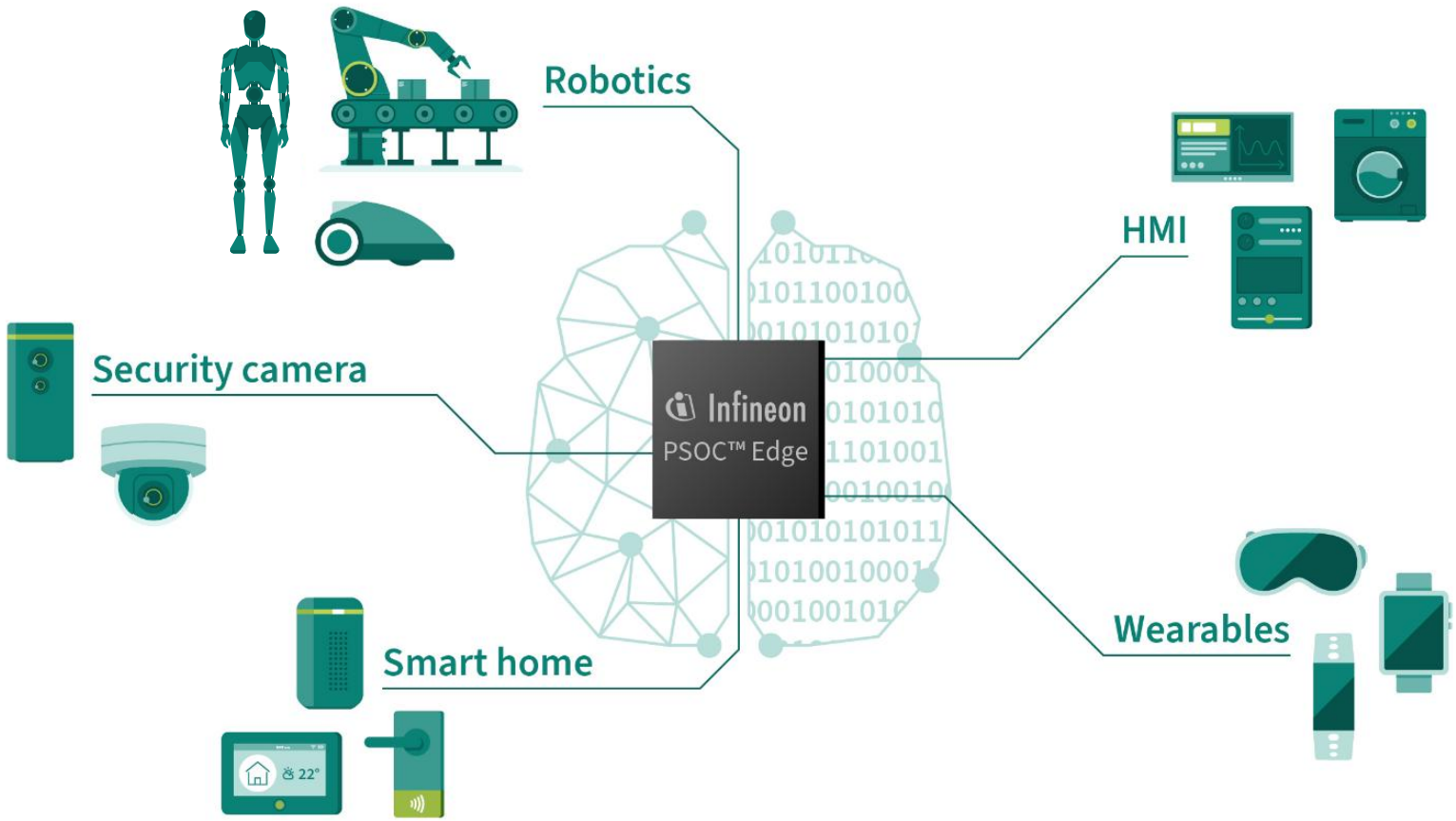
PSOC™ Edge

PSOC™ Control

PSOC™ Connect

- Broad application range in **Edge AI**, **IoT, Consumer**, and **Industrial**
- Strength in **low power**, **high performance**, **security**, and **reliability**
- Roadmap focus on **AI**, **security**, and **integrated connectivity**

PSOC™ Edge – Enables a new generation of responsive machine learning devices

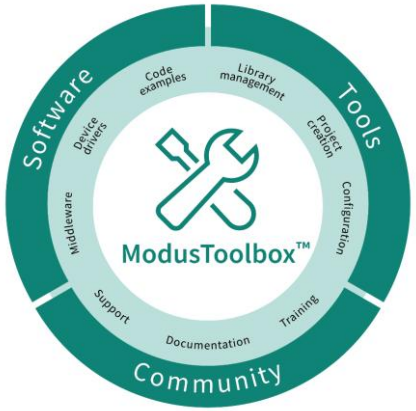


Software with maximal ease of use

DEEPCRAFT™ Studio

- Infineon's Edge AI development platform
- Data collection & pre-processing, model training, model conversion & deployment
- Provides AI-models for a wide variety of applications

ModusToolbox™



- Infineon's modern, extensible development system
- Collection of development tools, libraries, and embedded runtime assets

Full journey from Edge AI model development to embedded software with flexible entry

Build a model
Bring your own model — OR
Buy a Ready Model

❯

Optimize & validate your model

❯

Develop your embedded product with Infineon's MCUs

DEEPCRAFT™ Studio	DEEPCRAFT™ Studio + Modus Toolbox™	Modus Toolbox™

Enabling connectivity with Infineon's broad wireless portfolio for IoT, industrial, and automotive applications

Wireless connectivity portfolio & advancements in UWB

Wi-Fi AIROC™

- **Comprehensive Portfolio**: Wi-Fi 4,5,6/6E and connected MCUs
- **Ultra-low power** consumption
- **Integrated MCUs** for simplified IoT design
- Advanced Wi-Fi 6/6E with **future-ready Wi-Fi 7** capabilities

Bluetooth® AIROC™

- **Full-featured Bluetooth® portfolio** with SoCs and modules
- **Low-energy focus** for extended battery life
- **Long-range Bluetooth® Low Energy (LE)** for industrial and automotive applications

Wireless Connectivity

Wi-Fi- & Bluetooth® Combo AIROC™

- Combines Wi-Fi and Bluetooth® in one module for **dual-connectivity use cases**
- Pre-certified for **faster time to market**

Ultra Wideband (UWB)

- Acquisition of UWB pioneer **3db**
- **Target applications:** Car access and fine ranging

Infineon provides a comprehensive end-to-end embedded AI solution - CSS provides most essential building blocks

Edge AI solution offering

- **In-house AI Software DEEPCRAFT™ Studio**
- **Development & AI Ecosystem Modus Toolbox™**
- **Microcontroller PSOC™ & XMC™**
- **Connectivity & security solutions AIROC™ & OPTIGA™**
- **Sensors XENSIV™**

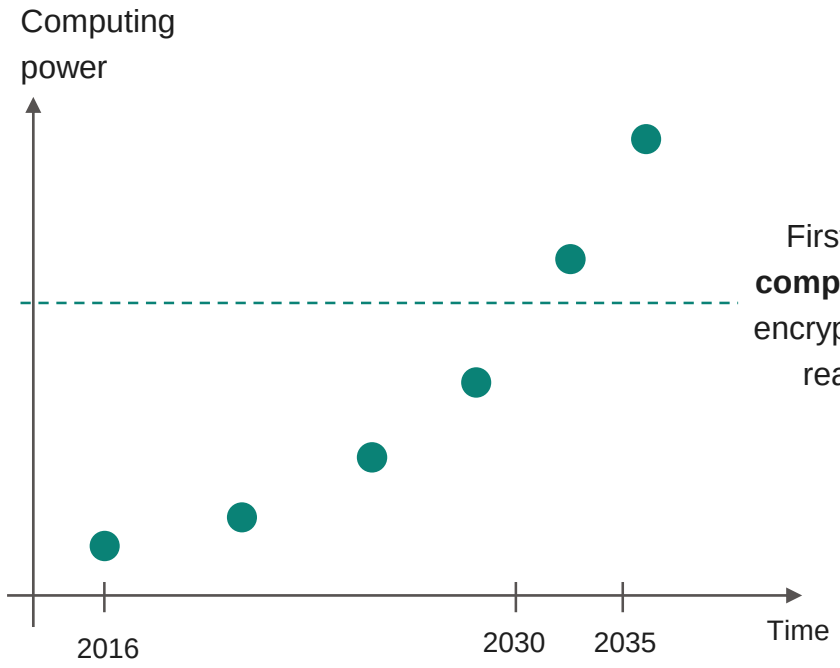
Customers‘ benefits

- Software perfectly tailored to Infineon hardware ensures **peak performance** and **simplified development**
- Comprehensive solutions **speed up time-to-market**
- Embedded AI solutions enable **edge processing**, **improving latency, and enhancing data privacy**
- Embedded AI solutions ensure smooth integration into **a wide range of applications**

Customer application

Infineon is a trusted advisor for the PQC landscape with the rise of quantum computers leading to high security risks

Computing power of quantum computers



First universal **quantum computers** breaking today's encryption methods could be ready by **2030 – 2035**

Cybersecurity

- **Asymmetric** encryption algorithms (e.g. RSA, ECC) loose appropriate security
- **Symmetric** encryption algorithms are less effected

Threats

- To **sensitive data** from governments and public institutions
- To **products** with long R&D cycles

Legislations

- Government bodies are **working on legislations** to prepare for quantum-safe future

Infineon's Post-quantum cryptography approach

Infineon is the **first company to receive the Common Criteria EAL6** for the implementation of **a PQC algorithm** in a security controller

Infineon **TEGRION™** product family of **next-gen security controllers** for long-lasting security and superior fault protection

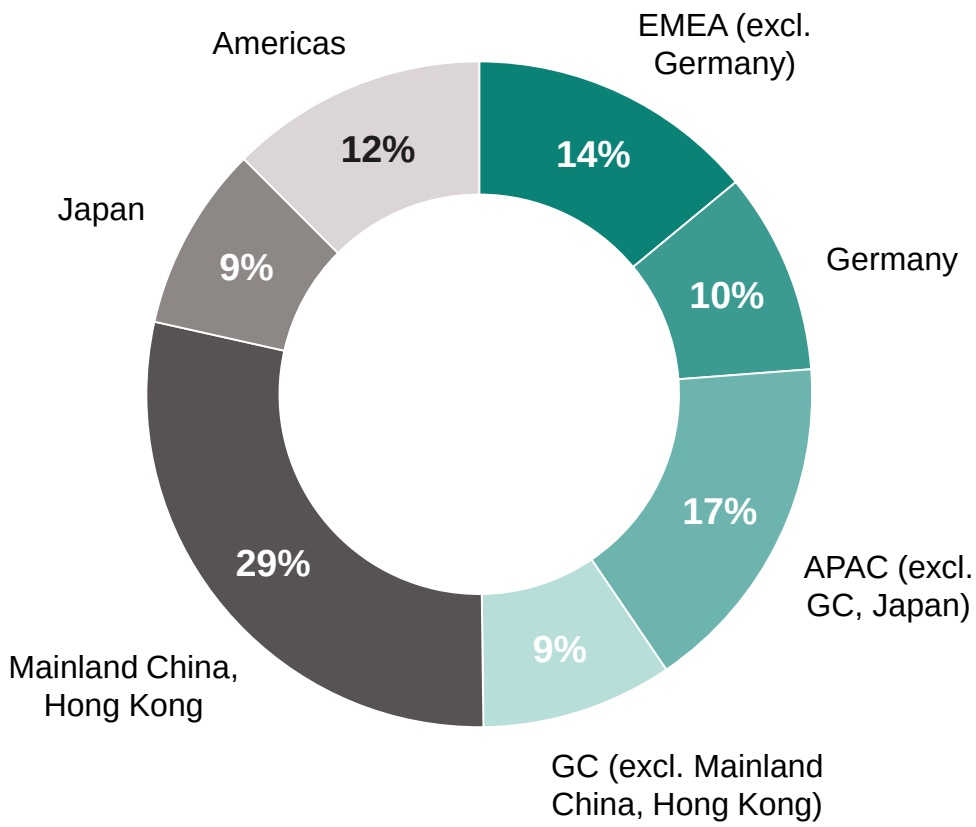
Partnering with customers, partners, and **the academic community** to prepare for a post-quantum future

Global team of experts and researchers dedicated to the PQC field

Selected financial figures

Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

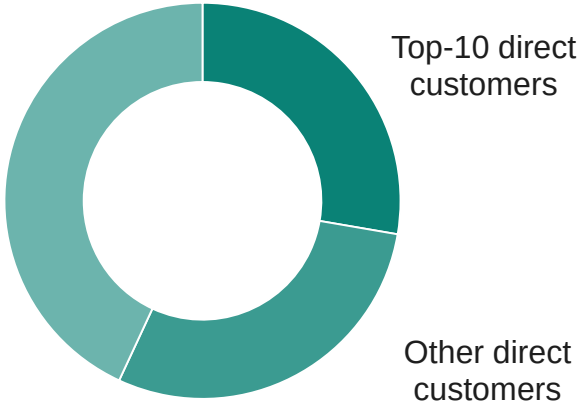
FY25 revenue by region



Revenue by sales channel

Distribution partners[1]

Top-10 direct customers[1]

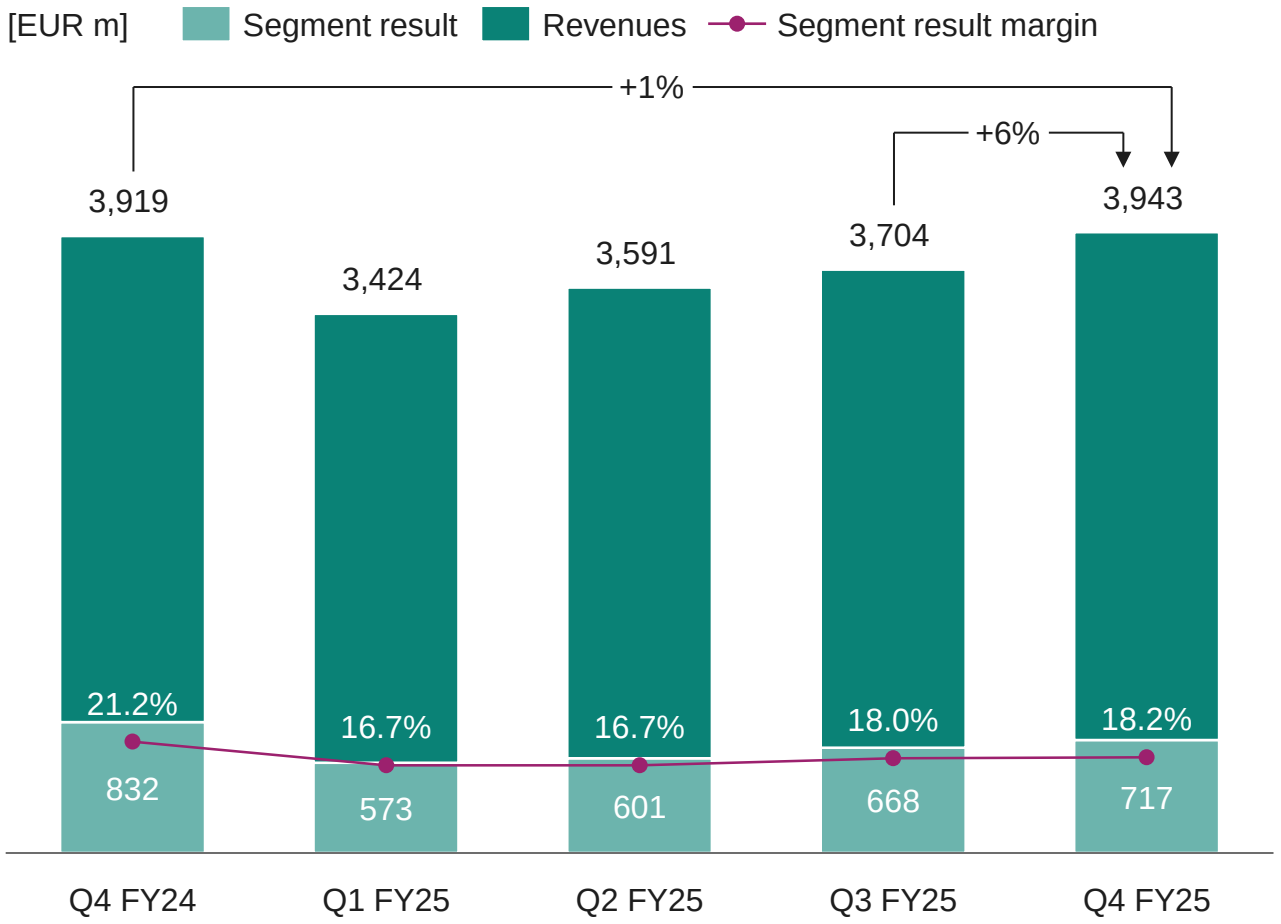


EMS partners[1]

[1] In alphabetical order

Group financial performance

Revenues and Segment Result

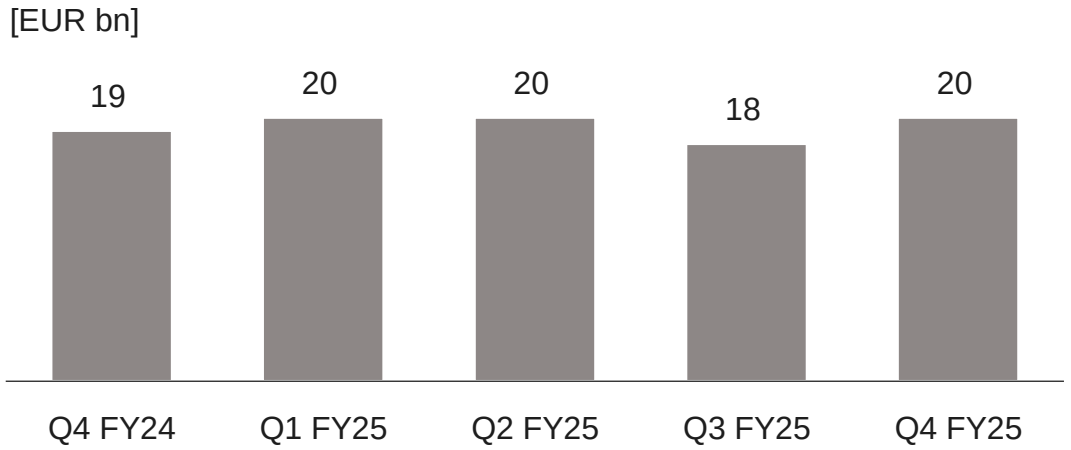


USD exchange rate

Average revenue exchange rate	FY24	FY25
ø USD/EUR	1.09	1.11

	Q4 FY24	Q3 FY25	Q4 FY25
	1.10	1.14	1.17

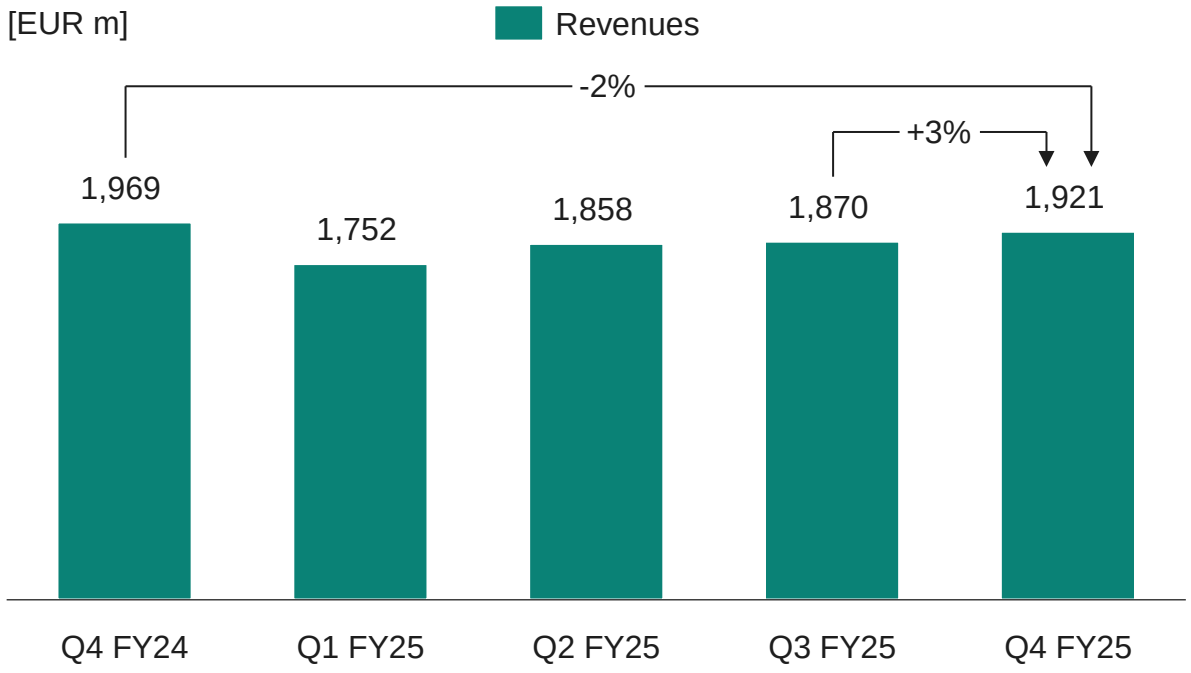
Order backlog[1]



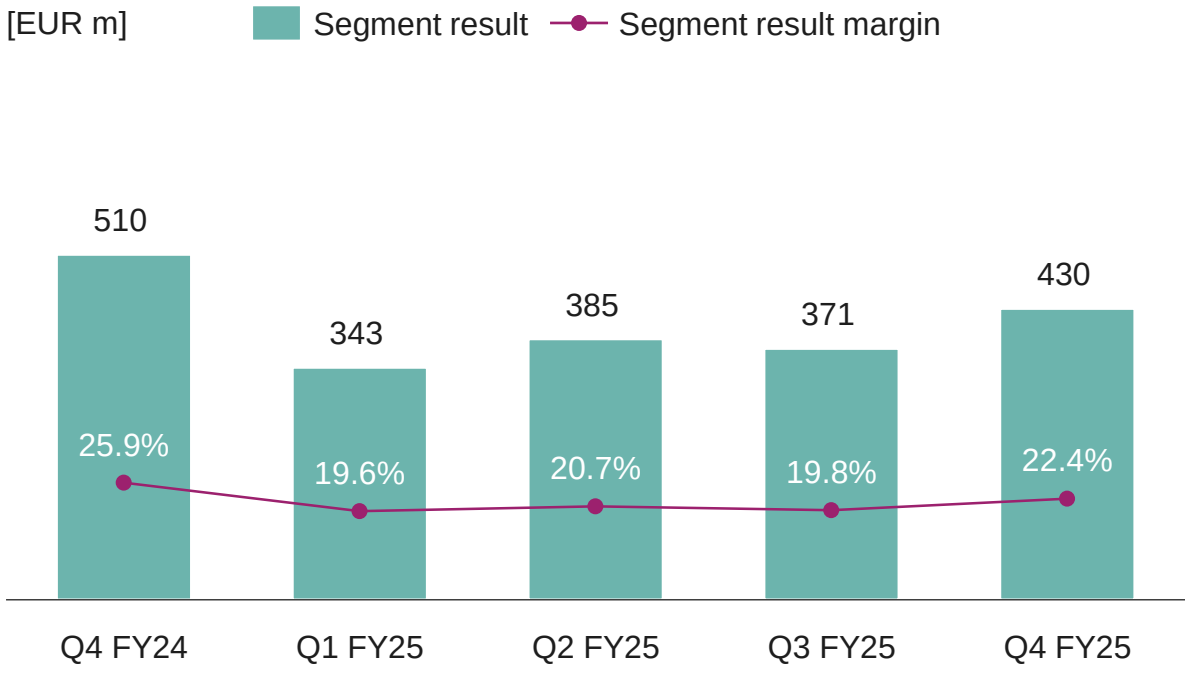
[1] See notes for definition

Automotive (ATV)

Revenues[1]



Segment Result[1]

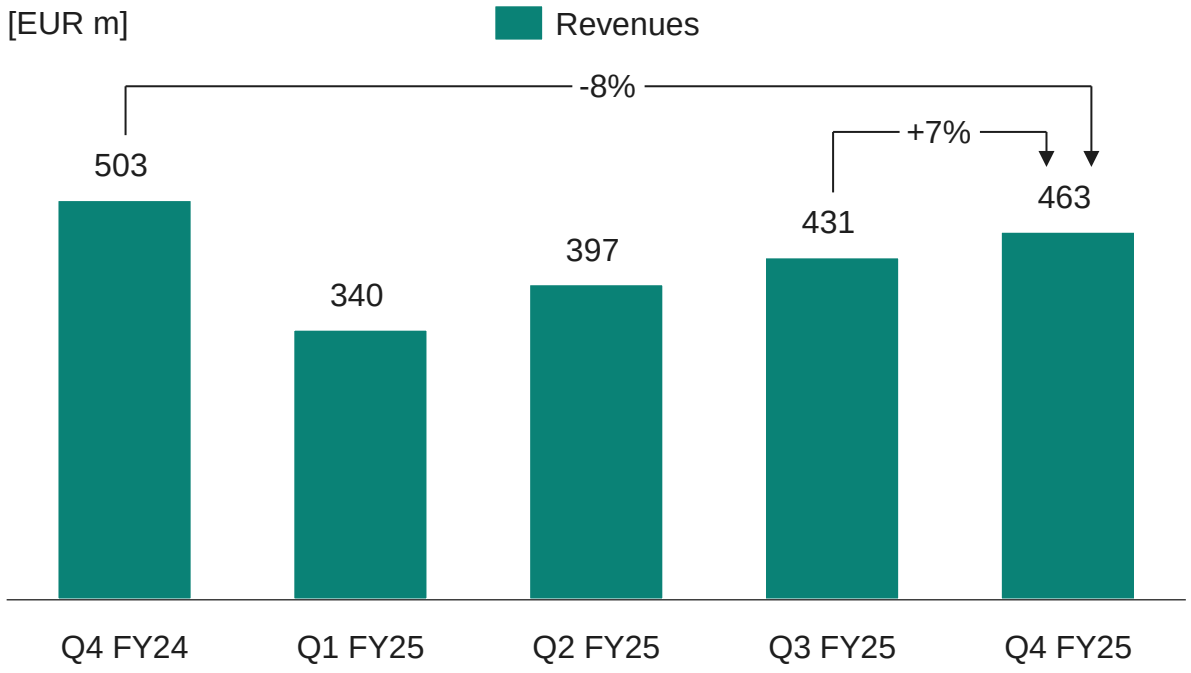


- Slight revenue increase driven by higher volumes, particularly in power components, MCUs and xEV (based on pull ins).
- Sequential segment result increase led mainly by volume and product mix-effects, as well as smaller positive non-recurring effects.
- We continue to shape the future of mobility with our market leading power, analog & sensor, control & connectivity portfolio.
- Ethernet solutions acquired from Marvell seeing great customer traction.

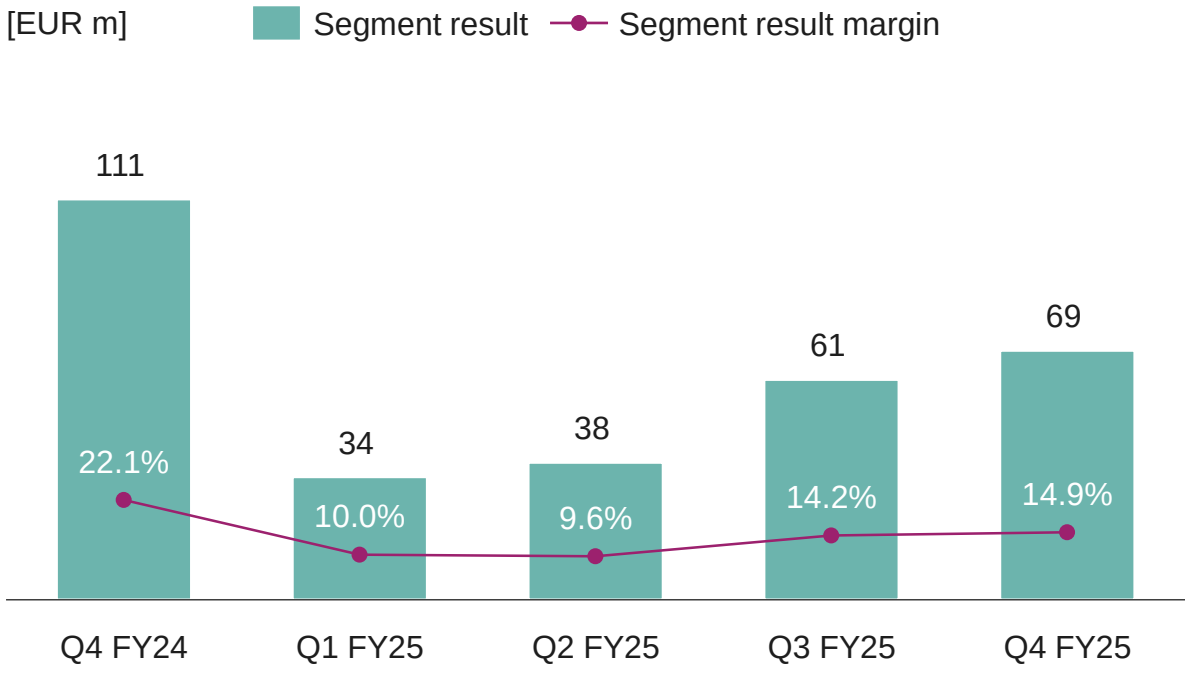
[1] Figures have been historically restated to reflect "Sense & Control" business line transfer of from ATV to PSS

Green Industrial Power (GIP)

Revenues



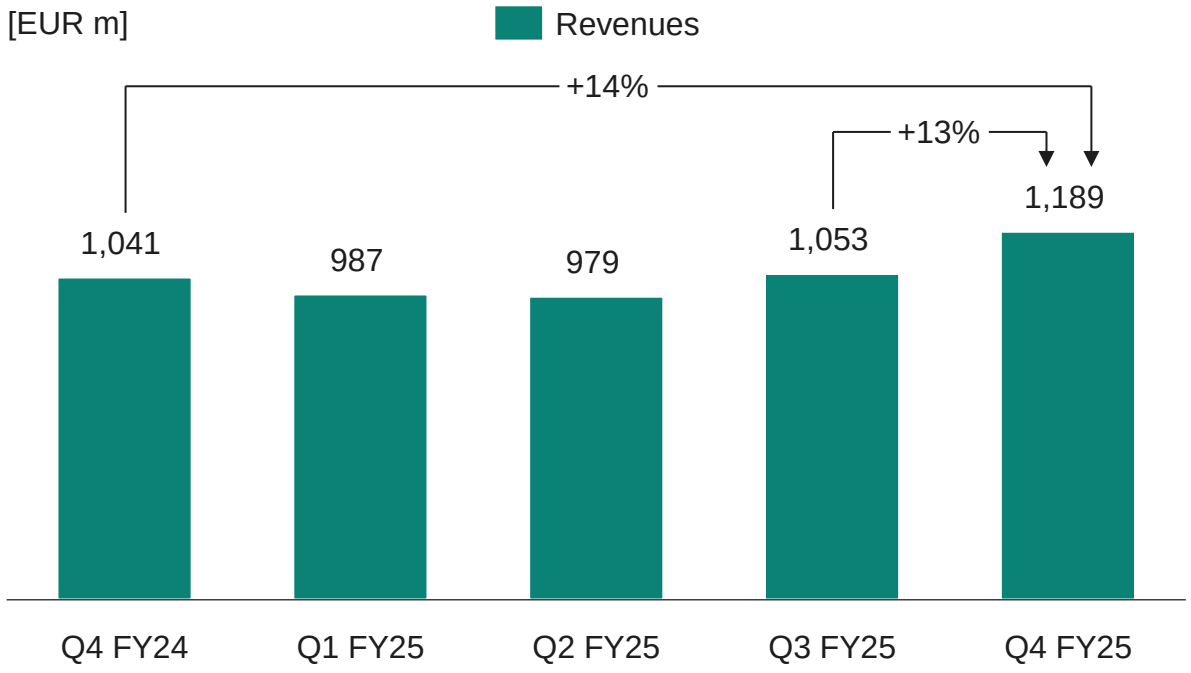
Segment Result



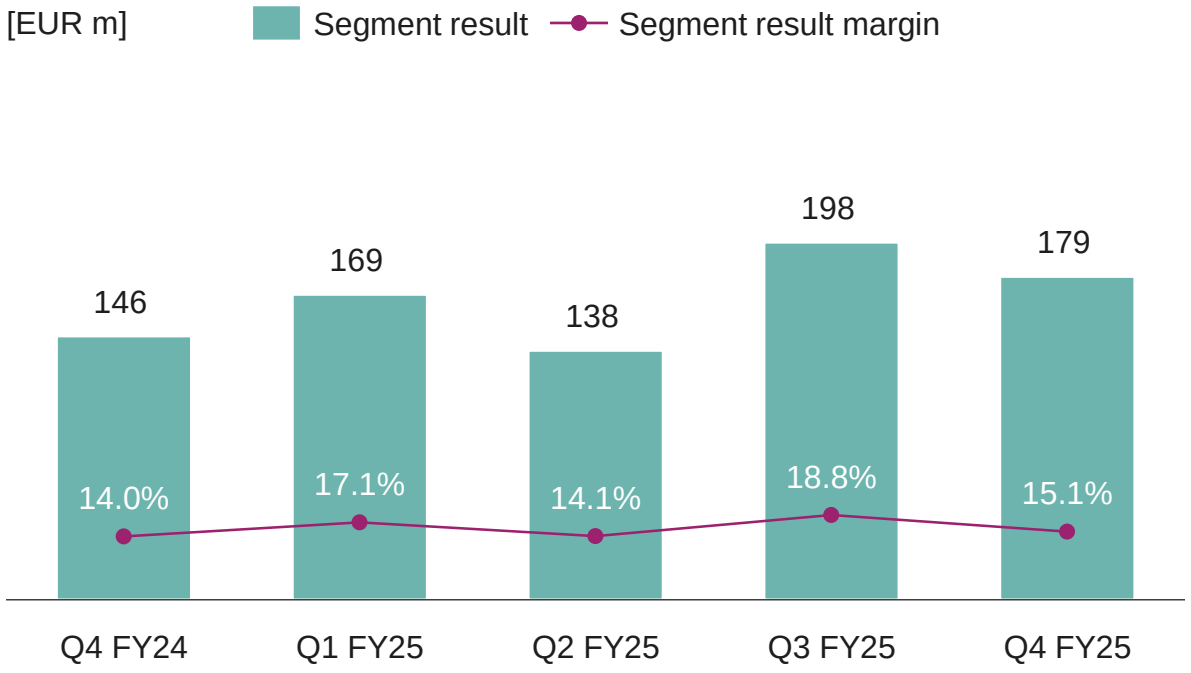
- Revenue improvement largely attributable to power infrastructure (renewables and grid infrastructure) and transportation.
- Segment result increase driven by revenue growth.
- Near term market situation for most industrial applications remains mixed.
- Structural drivers in grid infrastructure are strengthening as rising renewables share and AI data centers require significant grid upgrades.

Power & Sensor Systems (PSS)

Revenues[1]



Segment Result[1]

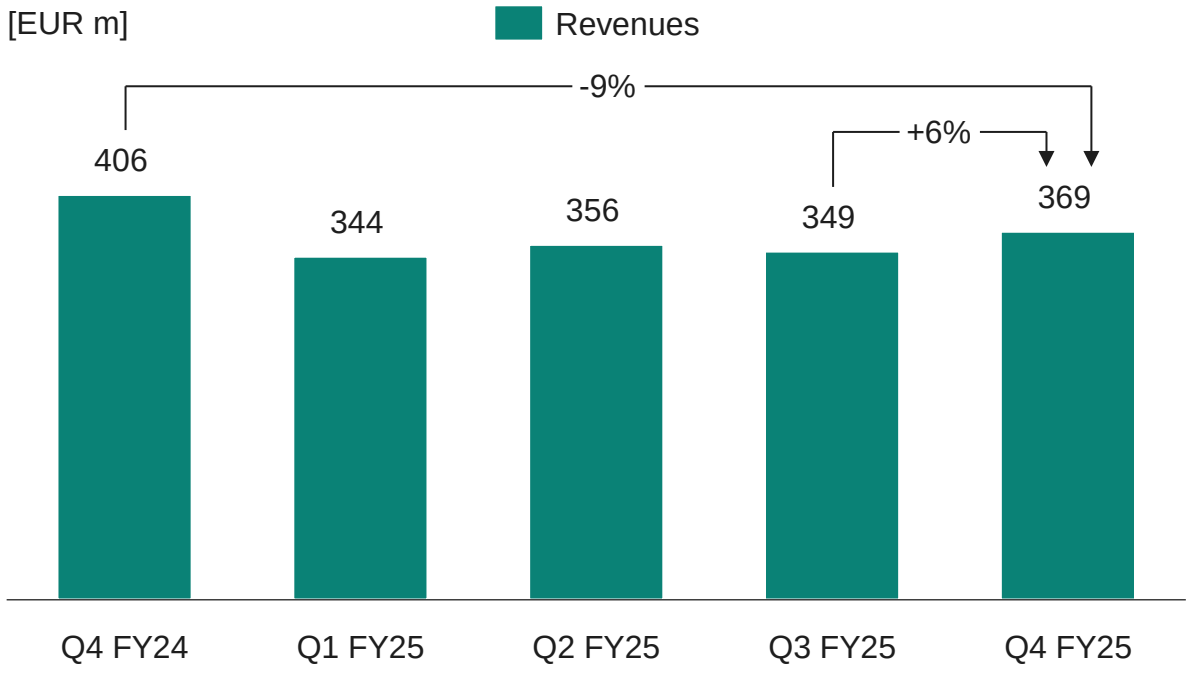


- AI power solutions remain the main revenue growth driver alongside tailwinds for smartphone/accessory products.
- Segment result margin adversely affected by exchange-rate headwinds and temporary “fab filler” deals.
- Consumer, general compute, and communications markets continue to show a tepid recovery.
- Very strong growth in AI-related markets continues – we expect to more than double our revenue to around €1.5bn next year!

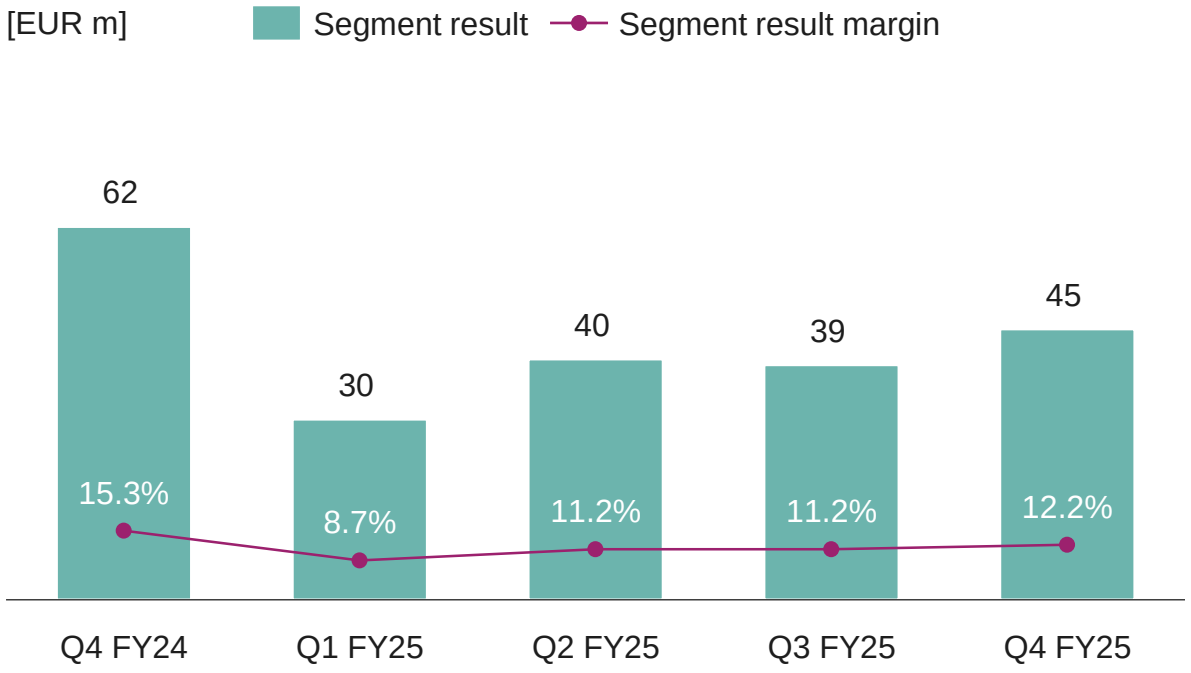
[1] Figures have been historically restated to reflect "Sense & Control" business line transfer from ATV to PSS

Connected Secure Systems (CSS)

Revenues



Segment Result

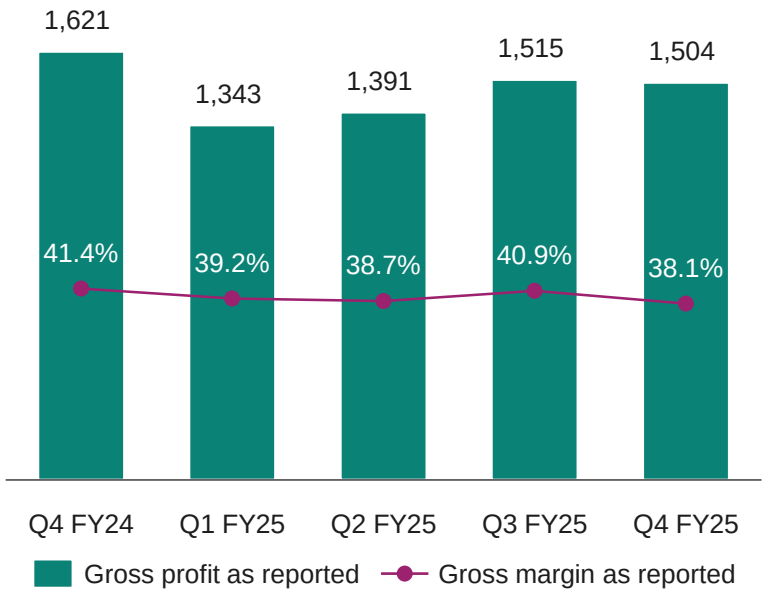


- Revenue increase driven by payment solutions, in part due to fulfillment of CRA orders.
- Segment result margin improved, led by higher revenue.
- Macroeconomic uncertainties persist, weighing on consumer and corporate spending, keeping IoT and security demand sluggish.

Gross margin and Opex

Gross profit[1]

[EUR m]



Therein Non-Segment Result charges
[EUR m]

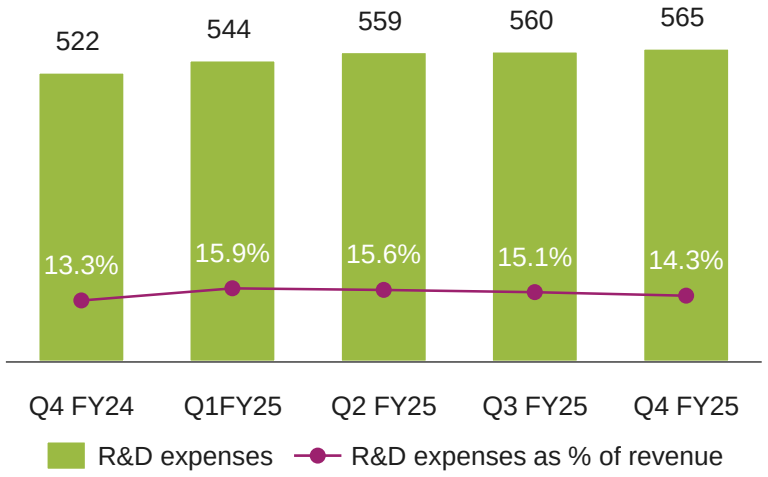
77	64	76	76	99

Adjusted gross margin [1]

43.3%	41.1%	40.9%	43.0%	40.7%

R&D[1]

[EUR m]

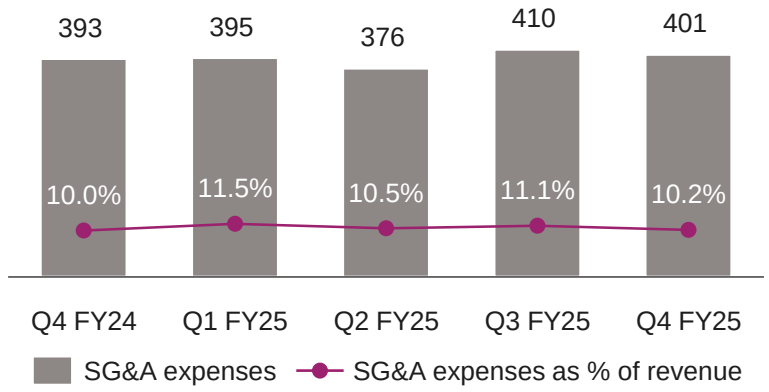


Therein Non-Segment Result charges
[EUR m]

14	18	14	18	17

SG&A

[EUR m]



Therein Non-Segment Result charges
[EUR m]

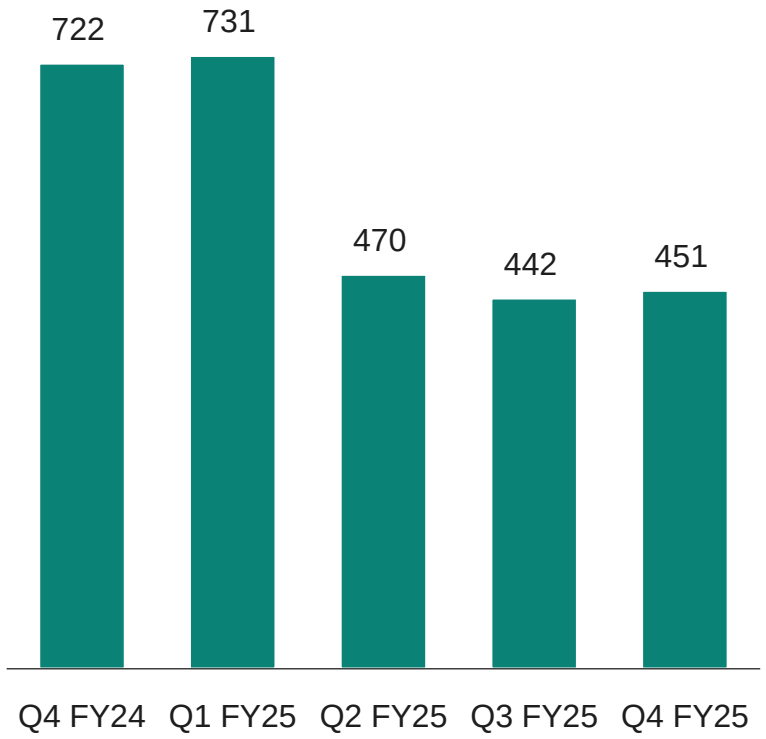
48	56	53	50	67

[1] To provide more meaningful information, Infineon changed its accounting policy on the allocation of certain expenses with effect from 1 October 2024. This resulted in expenses that were previously included in cost of goods sold being reclassified as research and development expenses. The prior-year figures have been adjusted accordingly.

Investments, Depreciation & Amortization and Free Cash Flow

Investments

[EUR m]

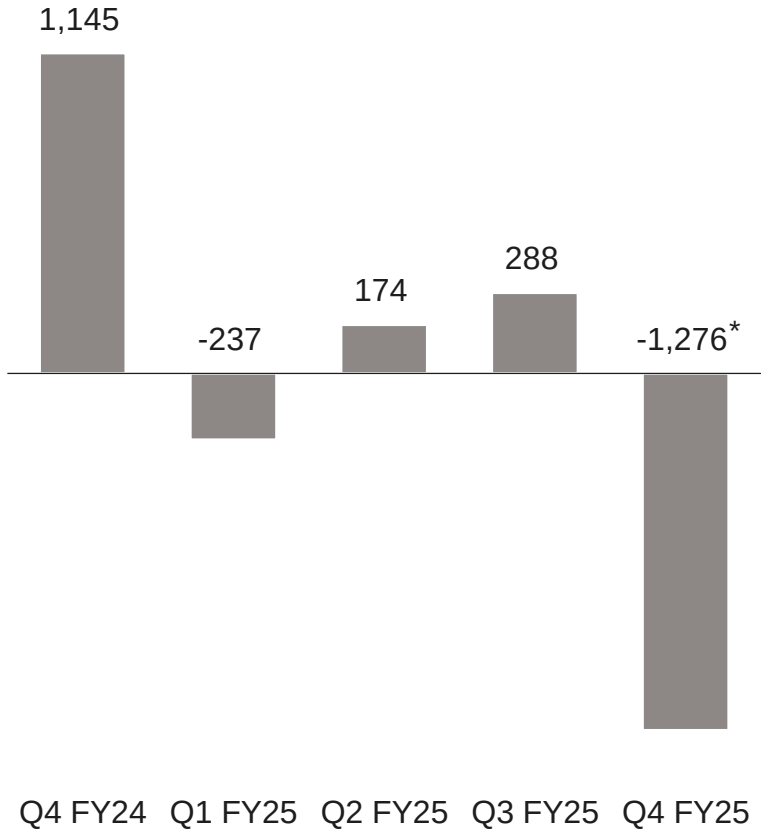


Depreciation & Amortization

[EUR m]

Free Cash Flow

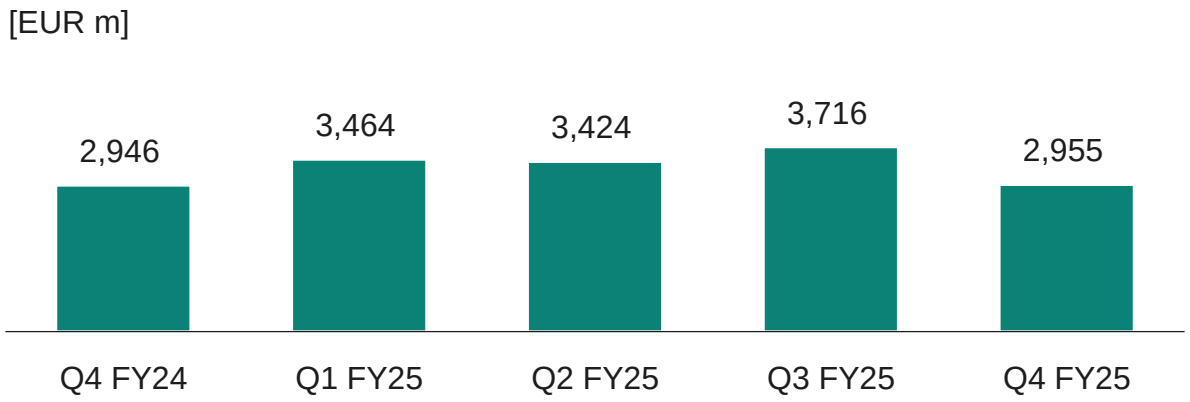
[EUR m]



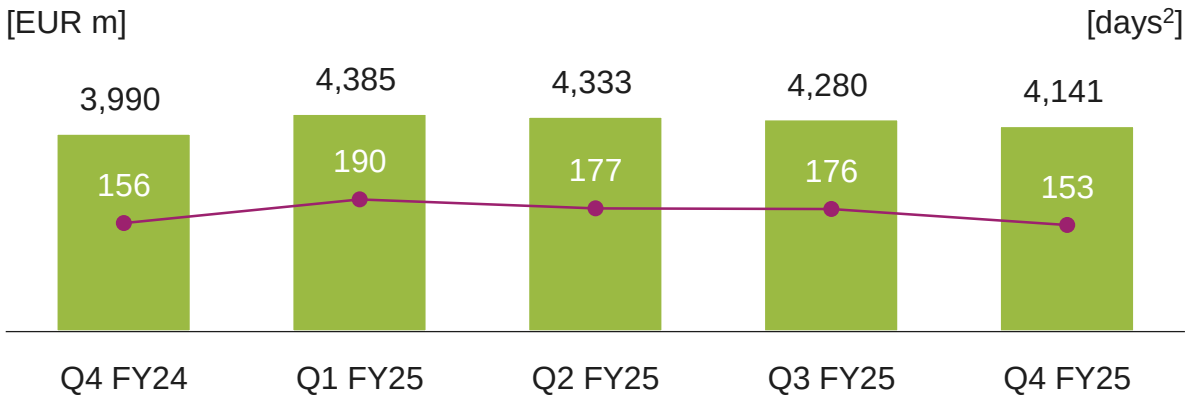
*FCF incl. 2,180m acquisition related outflows for Marvell's automotive Ethernet business

Working capital, in particular trade working capital components

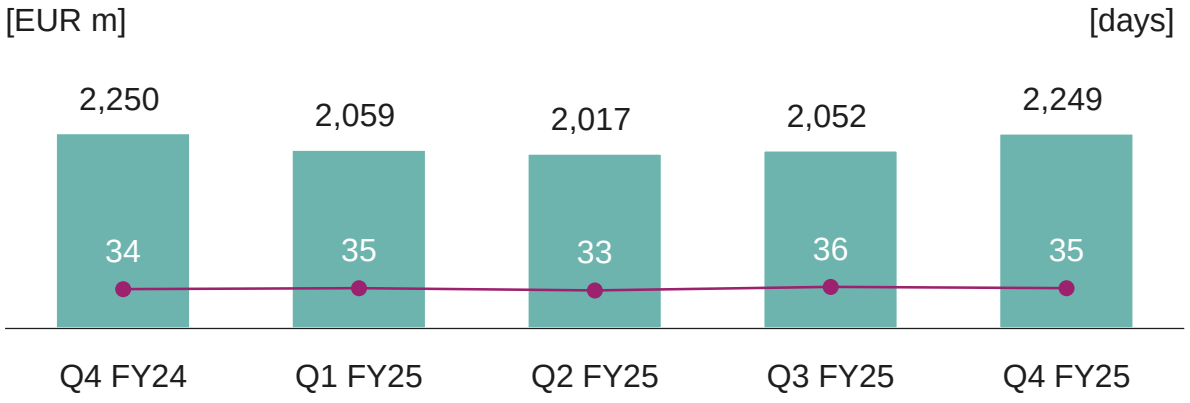
Working capital[1]



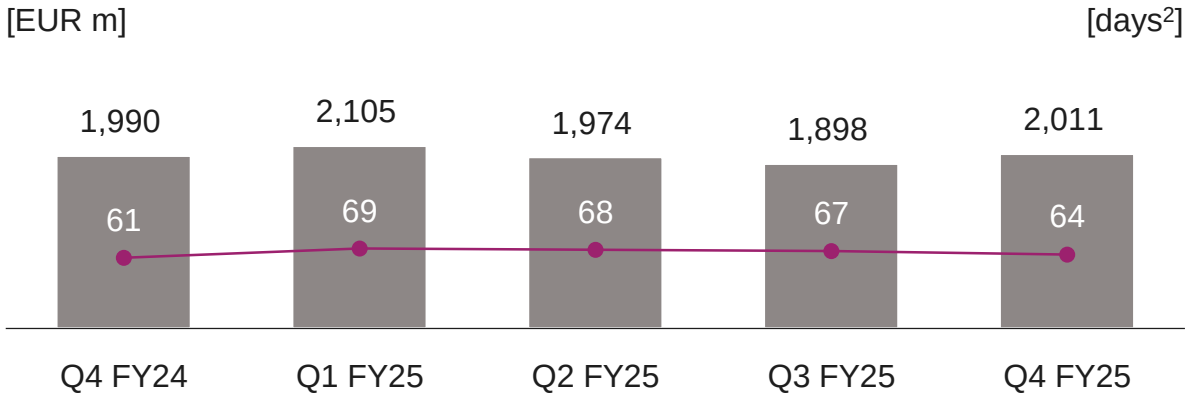
Inventories



Trade receivables



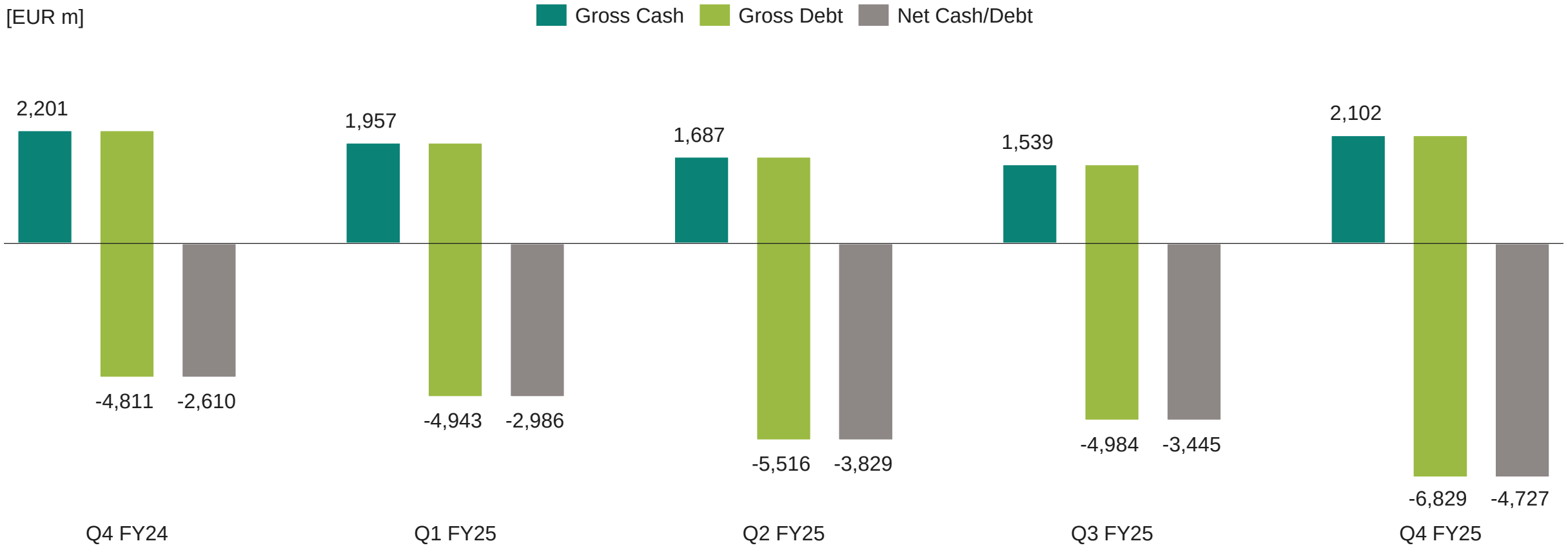
Trade payables



[1] See notes for definition
[2] To provide more meaningful information, Infineon changed its accounting policy on the allocation of certain expenses with effect from 1 October 2024. This resulted in expenses that were previously included in cost of goods sold being reclassified as research and development expenses. The prior-year figures have been adjusted accordingly

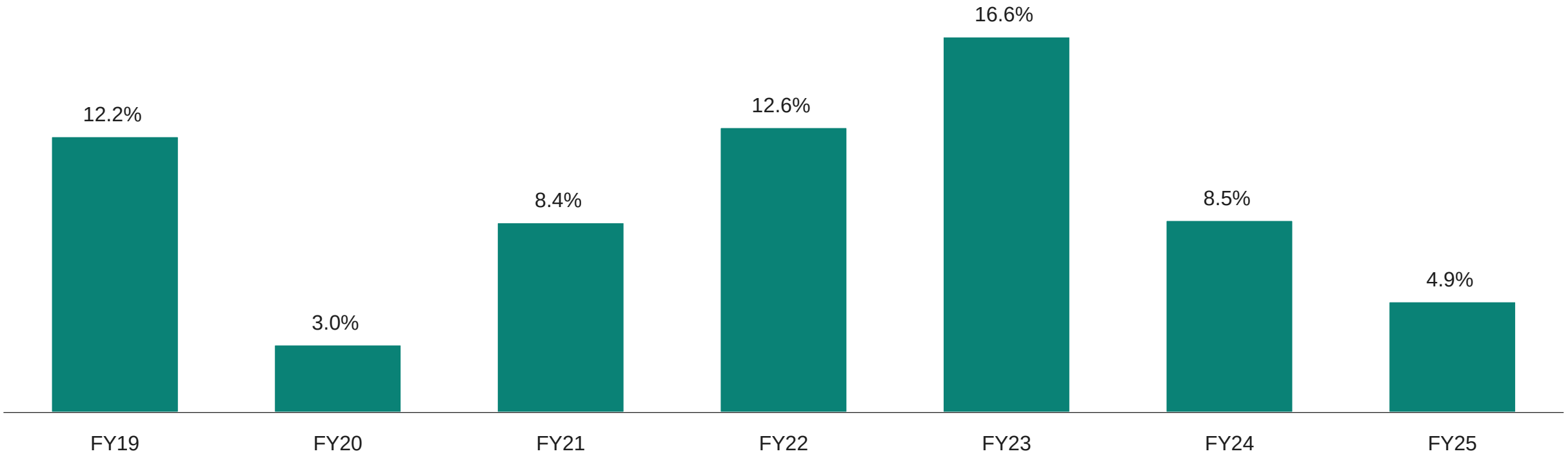
Development of liquidity and debt

Capital structure



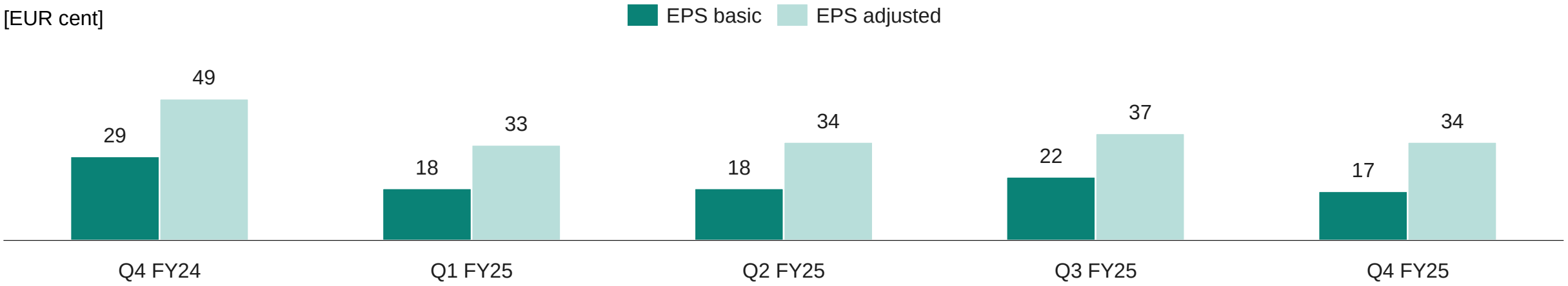
Return on capital employed

Historical development

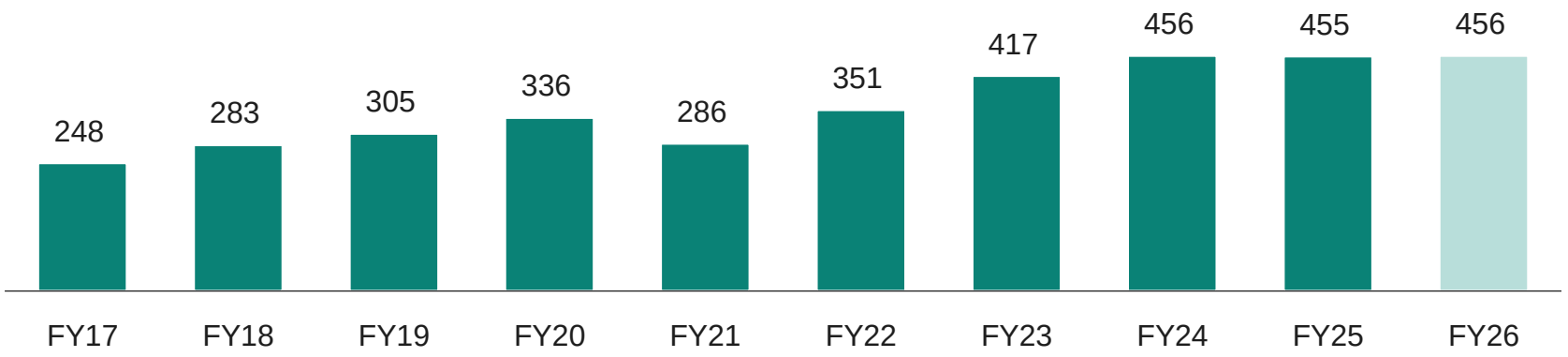


Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



Total cash return to shareholders via dividends

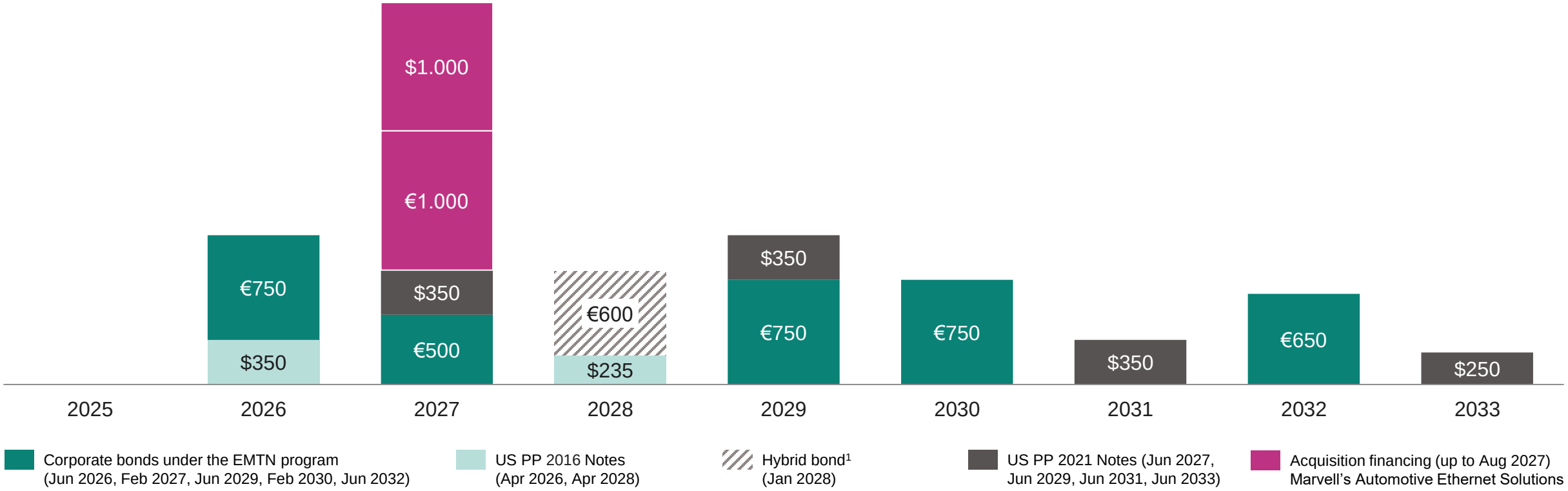


- Proposed dividend for FY25: €0.35 per share
- Payout of €456m

Maturity profile

Calendar years 2025 to 2033

[EUR m; USD m; nominal values]



[1] On 1 Oct 2019, Infineon issued a €600m perpetual hybrid bond with first call date in 2028; the hybrid bond is accounted as equity under IFRS.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility

	Financial Policy Targets	Status Quo (LTM 30 September 2025)
Gross Cash[1]	At least **10%** of revenue[3]	14% of revenue → **€2.1bn**
Gross Debt[2]	**≤ 2.0x** EBITDA	**2.0x** EBITDA
Comfortable liquidity position	– Flexibility for financing operating activities and investments through the cycle	
Balanced debt position	– Gross debt target commensurate with investment-grade rating	
Rating	Investment grade	**BBB+** stable outlook (by S&P Global Ratings)

[1] Gross cash position is defined as cash and cash equivalents plus financial investments | [2] Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization | [3] Gross cash target: At least 10 percent of revenue on average throughout the fiscal year


Infineon

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Disclaimer

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Glossary

AC	alternating current
ACC	adaptive cruise control
AD	automated driving
ADAS	advanced driver assistance system
AEB	autonomous emergency braking
APD	automotive power distribution
AR/VR	augmented/virtual reality
BEV	battery electric vehicle
BLE	Bluetooth low energy
BMS	battery management system
BoM	bill of materials
CAV	commercial, construction and agricultural vehicles
CMOS	complementary metal-oxide-semiconductor
DC	direct current
DSC/SSC	double/single sided cooling
E/E	electrical/electronic architecture
ECU	electronic control unit
EDC	electrical design current
eSE	embedded secure module
eSIM	embedded subscriber identity module
EMS	electronics manufacturing service
ESS	energy storage system
EV	electric vehicle
FCEV	fuel cell electric vehicle
FHEV/MHEV	full/mild hybrid electric vehicle
FoM	figure of merit
GaN	gallium nitride
HEMT	high-electron-mobility transistor
HID	human interface device
HMI	human machine interaction
HV	high voltage
HVAC	heating, ventilation, air conditioning
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	internet of things
IPM	intelligent power module
LED	light-emitting diode
MCU	microcontroller unit
MEMS	micro electro-mechanical system
MHA	major home appliances
MIMO	multiple input, multiple output
ML	machine learning
MNO	mobile network operator
MOSFET	metal-oxide silicon field-effect transistor
MV	medium voltage
NFC	near-field communication
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PD	power delivery
PHEV	plug-in hybrid electric vehicle
PHY	physical layer transceiver
PMIC	power management integrated circuits
PoL	point of load
PUE	power usage effectiveness
PSU	power supply unit
PV	photovoltaic
RAM	random access memory
RF	radio frequency
SAE	Society of Automotive Engineers
SDK	software development kit
Si	silicon
SiC	silicon carbide
SNR	signal-to-noise ratio
SoC	system-on-chip / state of charge
TDC	thermal design current
ToF	time-of-flight
UWB	ultra-wideband
WBG	wide-band gap, specifically referring to SiC and GaN based devices

Notes and ESG footnotes

Investments =	'Purchase of property, plant and equipment' + 'Purchase of intangible assets and other assets' incl. capitalization of R&D expenses
Adjusted Free Cash Flow Margin =	Adjusted for large investments in frontend buildings and major M&A transactions, for full definition see chapter "Internal management system" in the annual report
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale – ('Total Current liabilities' – 'Short-term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
RoCE =	Operating profit from continuing operations after tax/Capital Employed = (‘Operating profit' – ‘Financial result excluding interest result' – 'Share of profit (loss) of associates and joint ventures accounted for using the equity method'-'Income tax')/Capital Employed
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investment' – 'Assets classified as held for sale’) – ('Total current liabilities' – 'Short term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories'/'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables'/['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables’ - ‘reimbursement obligations’)[1]/'revenue' x 90

Order backlog =	The total amount of orders received regardless of their current status

ESG footnotes:

1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.
2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO_2 savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO_2 savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.
3) Carbon neutrality is defined in terms of Scope 1 and Scope 2 emissions.

[1] Without debtors with credit balances

Financial calendar

Date	Event	Location
13 – 14 November 2025	Morgan Stanley European TMT Conference	Barcelona
17 November 2025	JP Morgan Global TMT Conference	Hong Kong
26 – 27 November 2025	We Power AI – Divisional Update Call with Peter Wawer, Head of GIP and Adam White	London
1 – 2 December 2025	UBS Global TMT Conference	Scottsdale
4 December 2025	Bernstein Premium Review Conference	Paris
8 – 9 January 2026	Oddo BHF Forum	Lyon
4 February 2026[1]	Earnings release for the first quarter of the 2026 fiscal year	
19 February 2026	Annual General Meeting 2026	Munich
6 May 2026[1]	Earnings release for the second quarter of the 2026 fiscal year	

[1] Preliminary

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